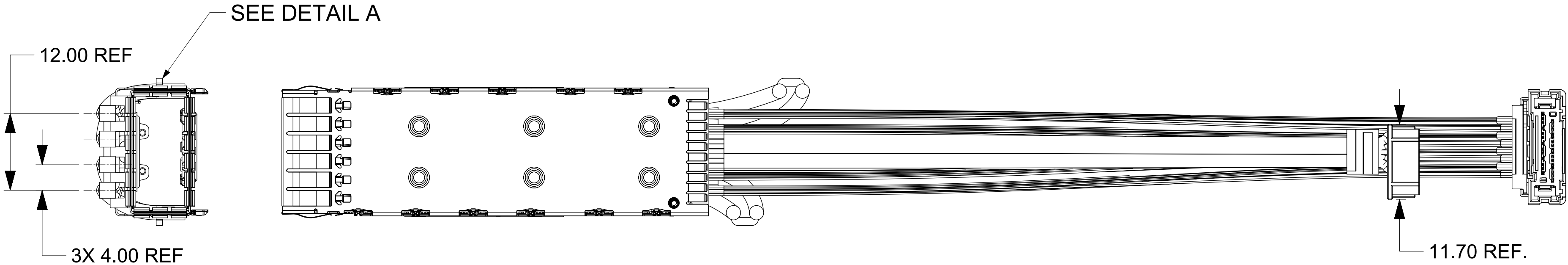
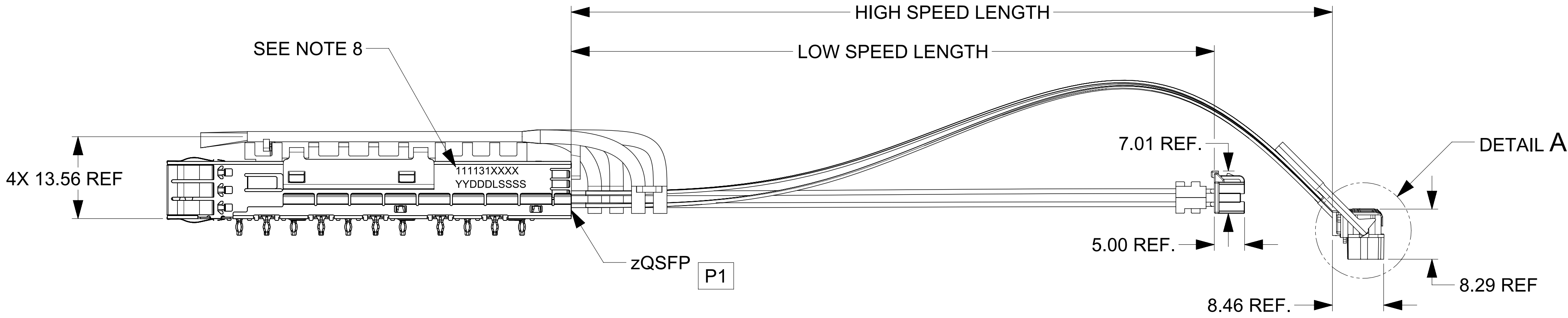


ENHANCED zQSFP+ 1X1 CAGE TO
NEARSTACK (1) PICO-CLASP (1)
CABLE ASSEMBLY

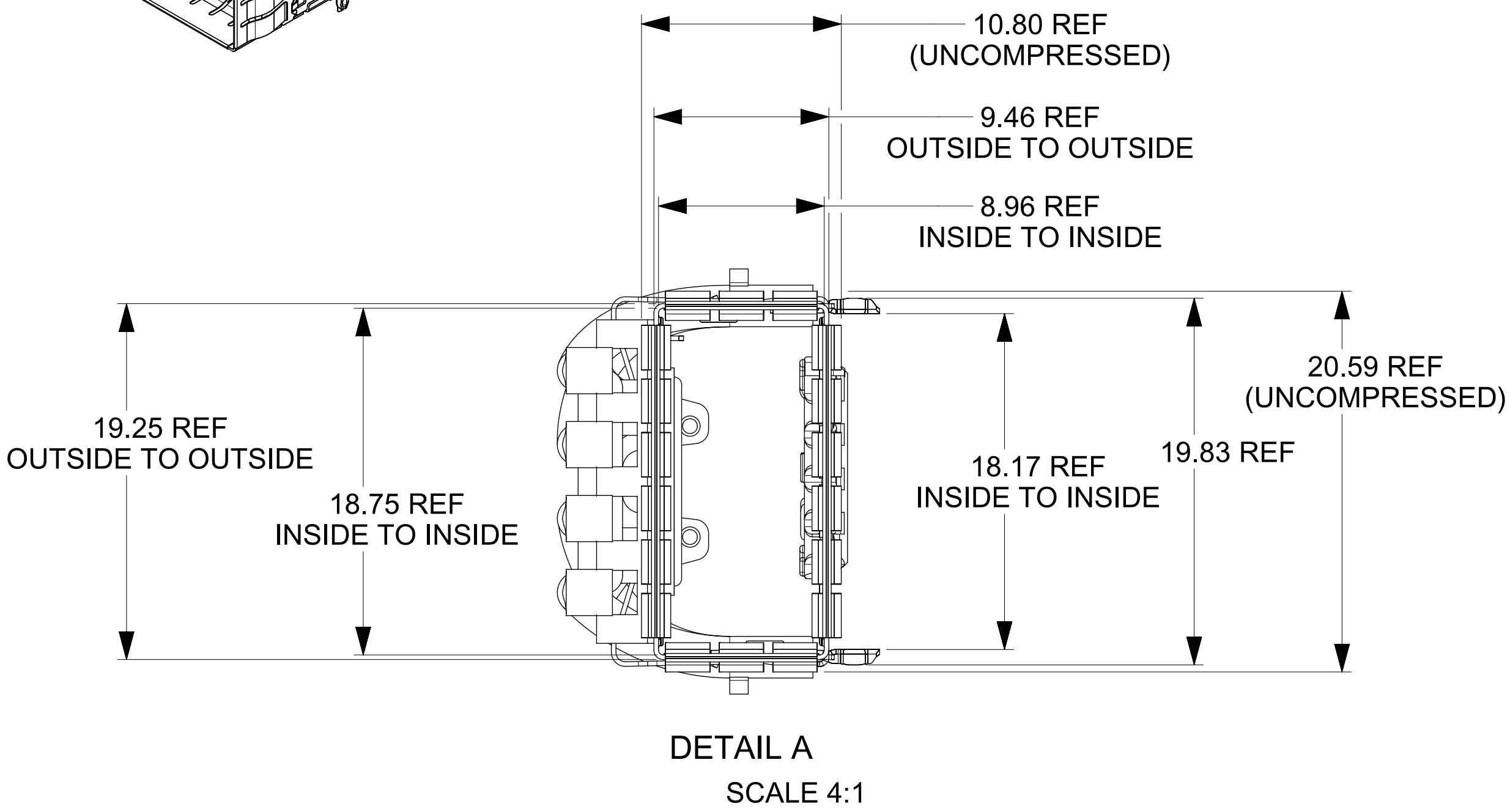
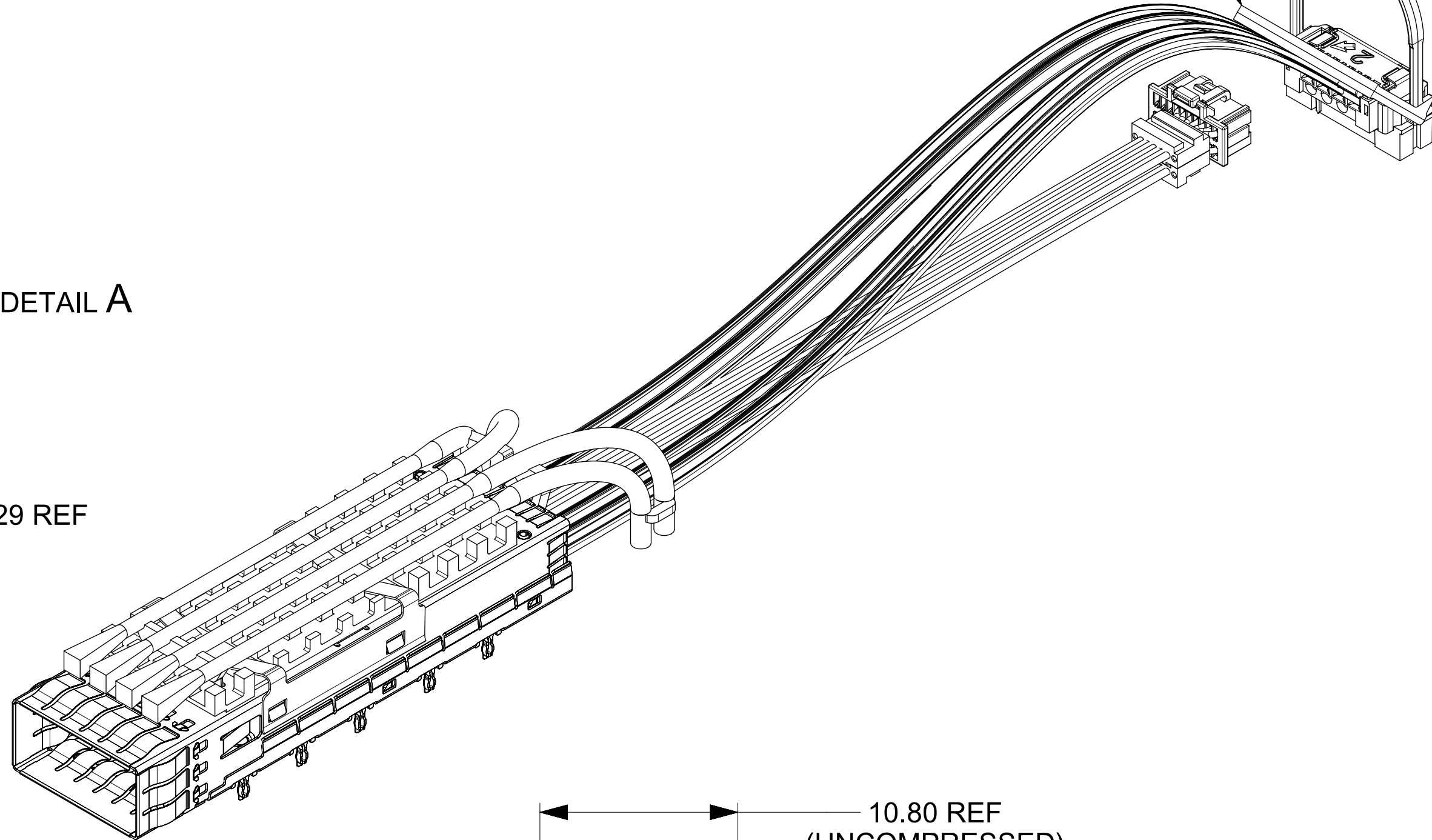
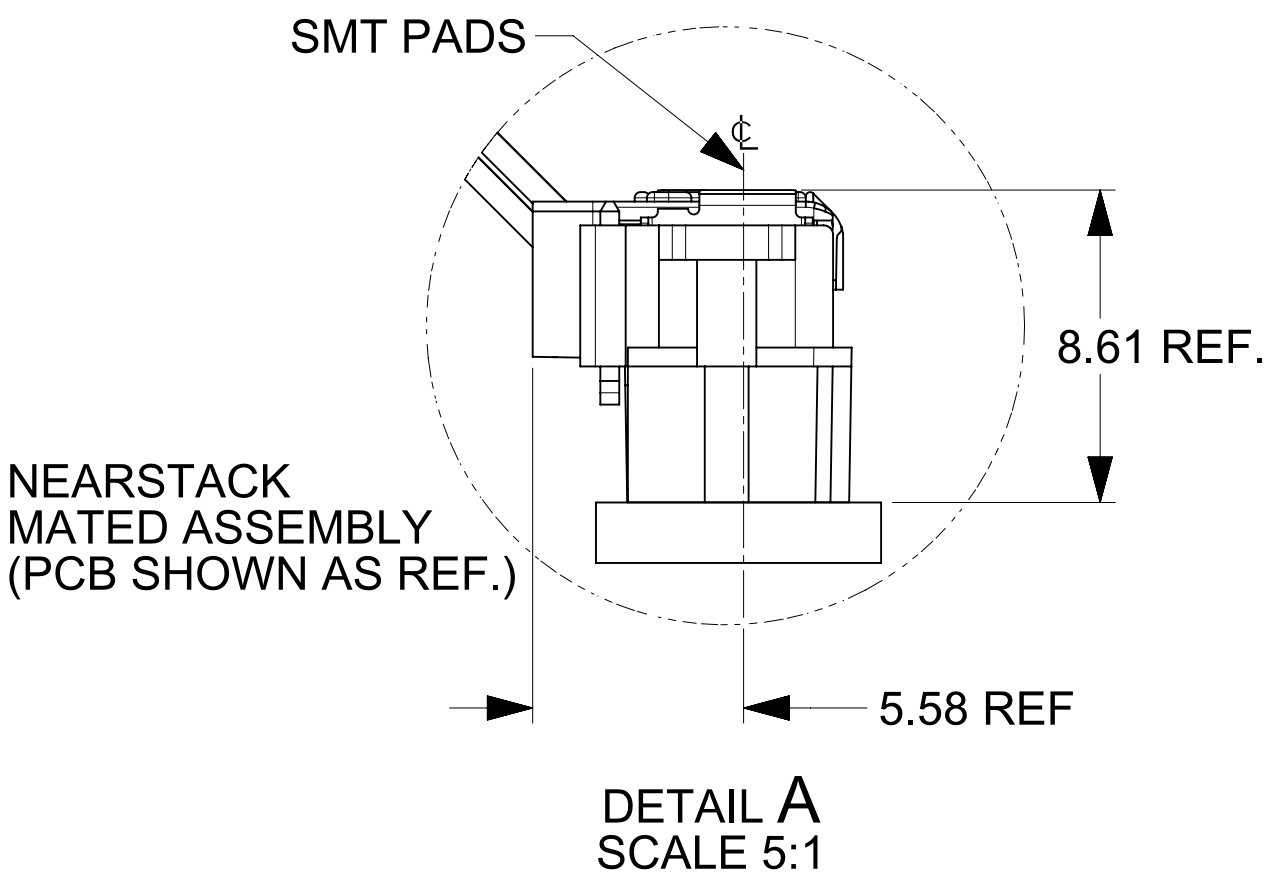


PULL BAILE SHOWN
IN UP POSITION

PULL BAILE SHOWN
IN DOWN POSITION
LIMITED BY TWINAX

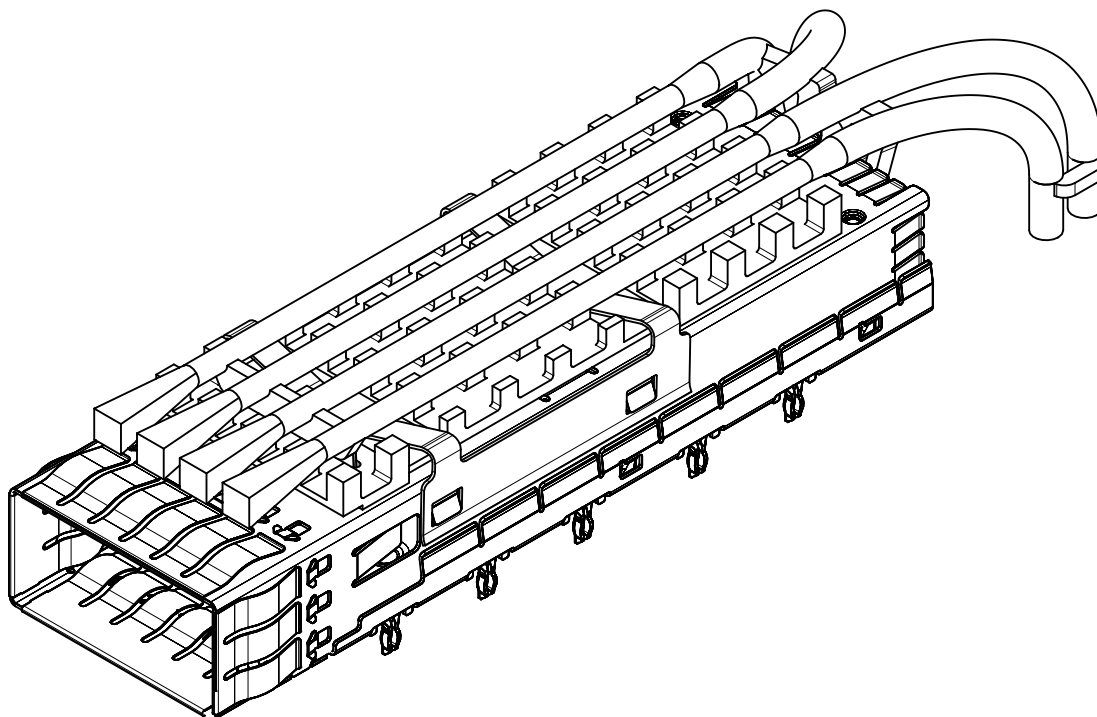
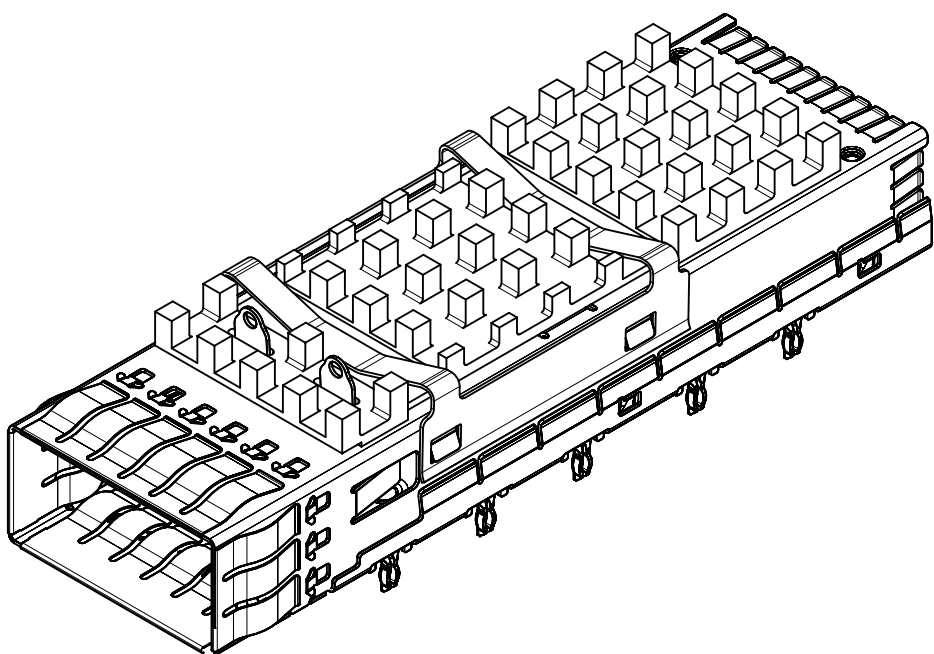
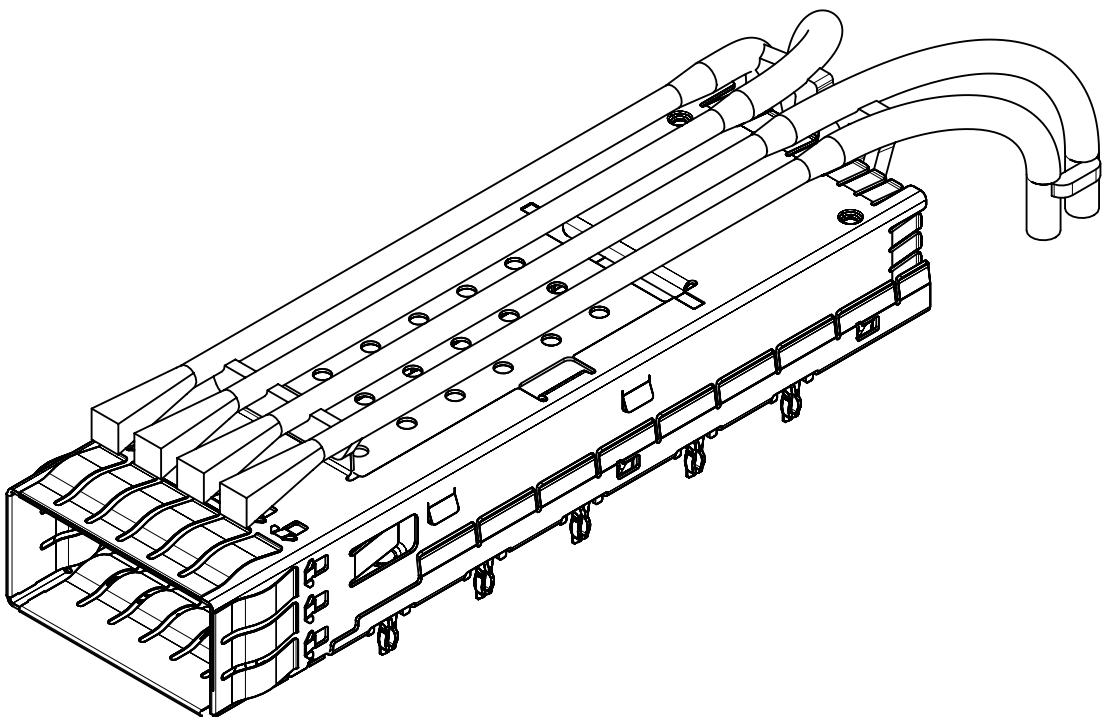


- NOTES:
- CABLE LENGTH DEPENDS ON WIRE GAUGE, DATA RATE AND HOST BOARD DRIVER CAPABILITIES.
 - MATERIALS:
 - CAGE - STAINLESS STEEL
 - HEAT SINK - ALUMINUM
 - LIGHT PIPE - TRANSPARENT POLYMER
 - TWINAX CABLE (HIGH SPEED)
 - SHIELD - ALUMINUM/POLYESTER FOIL WRAP
 - SIGNAL PAIR - 34AWG SOLID SILVER PLATED COPPER
 - DRAIN - 34AWG SOLID SILVER PLATER COPPER
 - CONFORMS TO UL VW-1
 - IMPEDENCE - 100 OHMS
 - COLOR: YELLOW
 - DISCRETE CABLE (LOW SPEED)
 - INSULATION - XLPE
 - CONDUCTOR - 28AWG SOLID SILVER PLATED COPPER
 - COLOR: BLACK
 - PRESS FIT LEGS 2.44 [0.096] LONG.
 - 1.57 [0.062] MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.
 - 3.00 [0.118] MINIMUM PCB THICKNESS FOR BELLY TO BELLY USE.
 - P2: BOTH NEARSTACK RECEPTACLE MOLEX PN 2042731100 (GEN 2.0)
MATES WITH NEARSTACK PLUG PN 2033162200 (GEN 2.0).
P3: MOLEX PN 5011892010 UTILIZING TERMINAL PN 5011939000 (GOLD PLATED ON CRIMP BARREL)
MATES WITH PN 5011902017.
 - RoHS COMPLIANT. NO EXEMPTIONS.
 - MARK WITH PART NUMBER SERIAL NUMBER
PART NUMBER: SEE PART NUMBER TABLE
SERIAL NUMBER:
YY - YEAR
DDD - DAY OF THE YEAR
L - MANUFACTURE LOCATION
SSSS - SERIAL NUMBER (0001-9999)



THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
FUNCTIONAL SYMBOLS F A = 0 F C = 0 F P = 0 DIVISIONAL SYMBOLS	DIMENSION UNITS MM		SCALE 2:1		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex							
	GENERAL TOLERANCES (UNLESS SPECIFIED)														
	ANGULAR TOL ± 0.5°														
	4 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04			PRODUCT SALES DRAWING							
	3 PLACES		±												
	2 PLACES		±												
	1 PLACE		±												
	0 PLACES		±												
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
						D-SIZE		111131				GENERAL MARKET		1 OF 17	

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



OPEN TOP WITH HEAT SINK AND LIGHTPIPE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111311911	75	150	OBSOLETE
1111311912	75	200	OBSOLETE
1111311913	75	300	OBSOLETE
1111311914	75	400	OBSOLETE
1111311915	75	500	OBSOLETE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111311970	75	150
1111311971	75	200
1111311972	75	300
1111311973	75	400
1111311974	75	500

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111311980	75	150
1111311981	75	200
1111311982	75	300
1111311983	75	400
1111311984	75	500

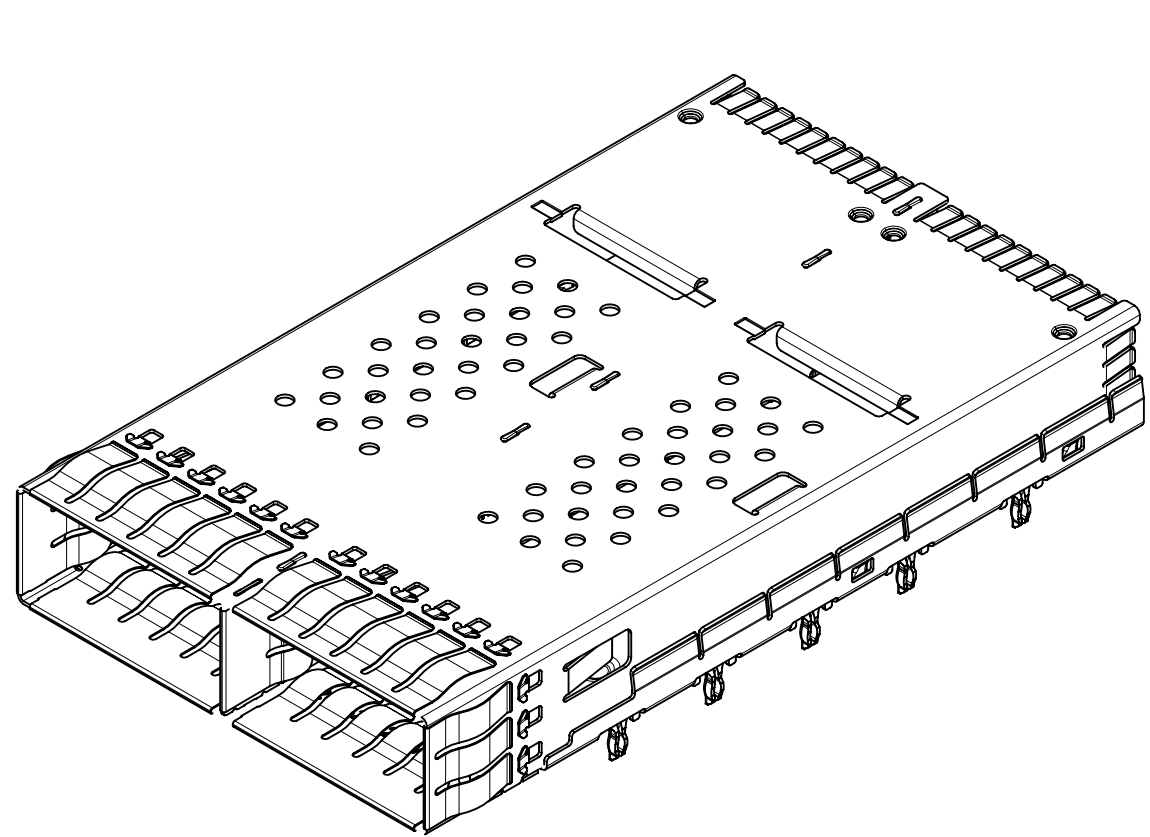
PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111311950	75	150
1111311951	75	200
1111311952	75	300
1111311953	75	400
1111311954	75	500

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

FUNCTIONAL SYMBOLS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
F = 0 F = 0 F = 0 DIVISIONAL SYMBOLS		DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]					molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP				
		GENERAL TOLERANCES (UNLESS SPECIFIED)													
		ANGULAR TOL ± 0.5°													
		4 PLACES		±											
		3 PLACES		±											
2 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04					PRODUCT SALES DRAWING						
1 PLACE		±							DOCUMENT NUMBER			DOC TYPE		DOC PART	REVISION
0 PLACES		±							1111310799			PSD		000	J1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						D-SIZE		111131				GENERAL MARKET		2 OF 17	

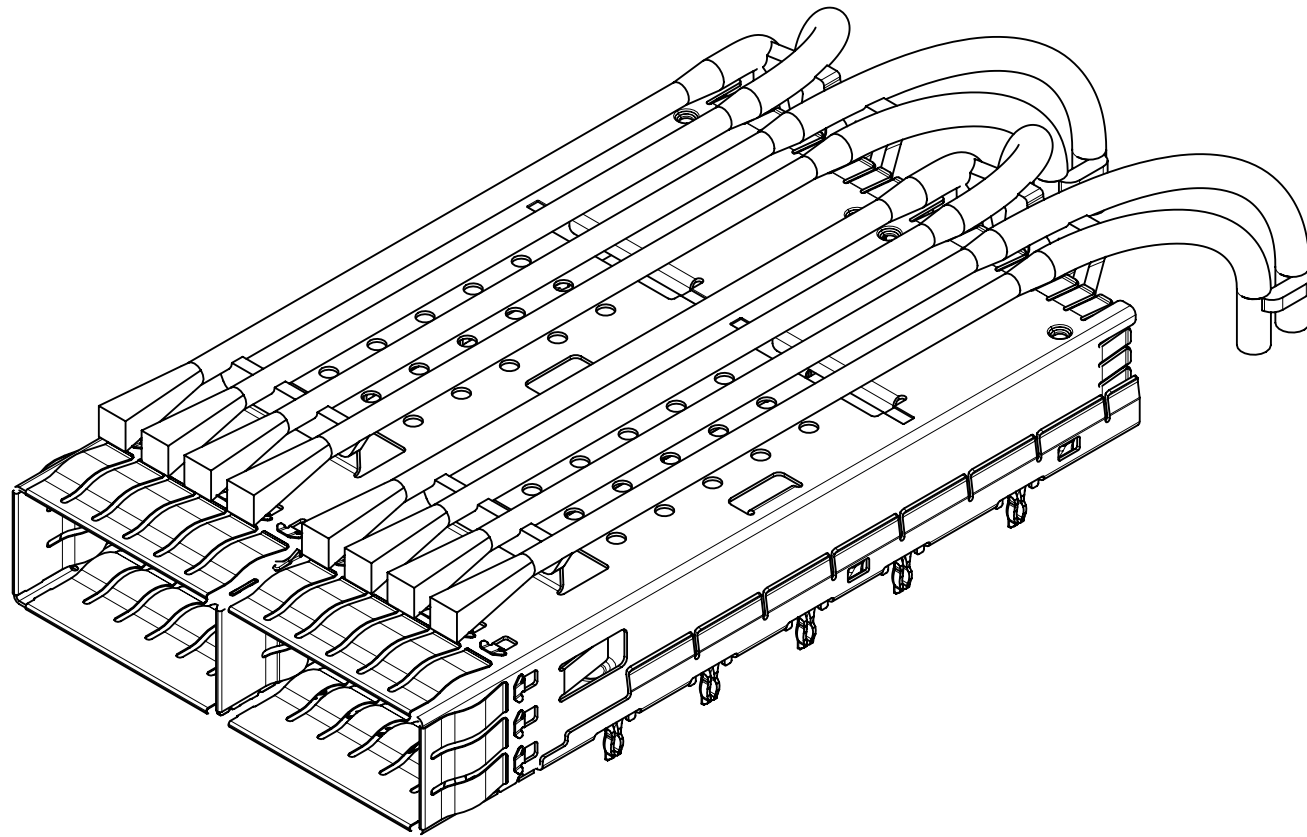
zQSFP BiPASS 1 X 2 CAGE ASSEMBLY

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



CLOSED TOP

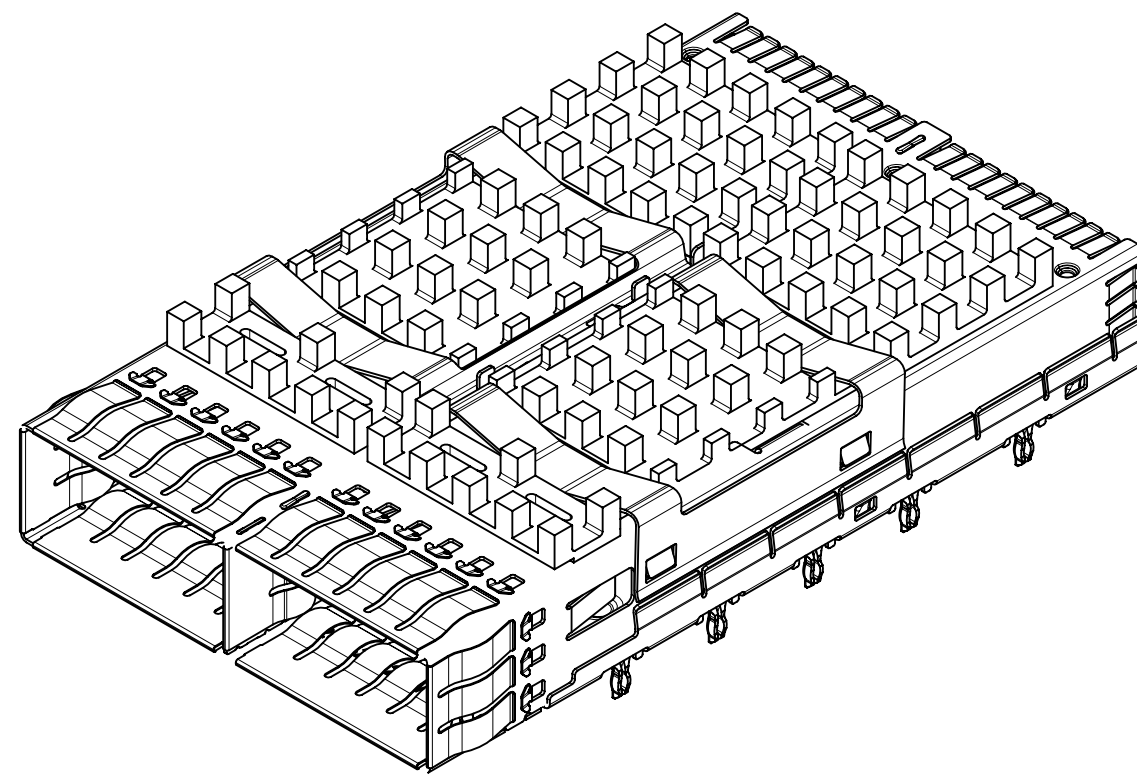
PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111313011	75	150	OBSOLETE
1111313012	75	200	OBSOLETE
1111313013	75	300	OBSOLETE
1111313014	75	400	OBSOLETE
1111313015	75	500	OBSOLETE
1111313016	75	210	OBSOLETE



CLOSED TOP WITH LIGHTPIPE

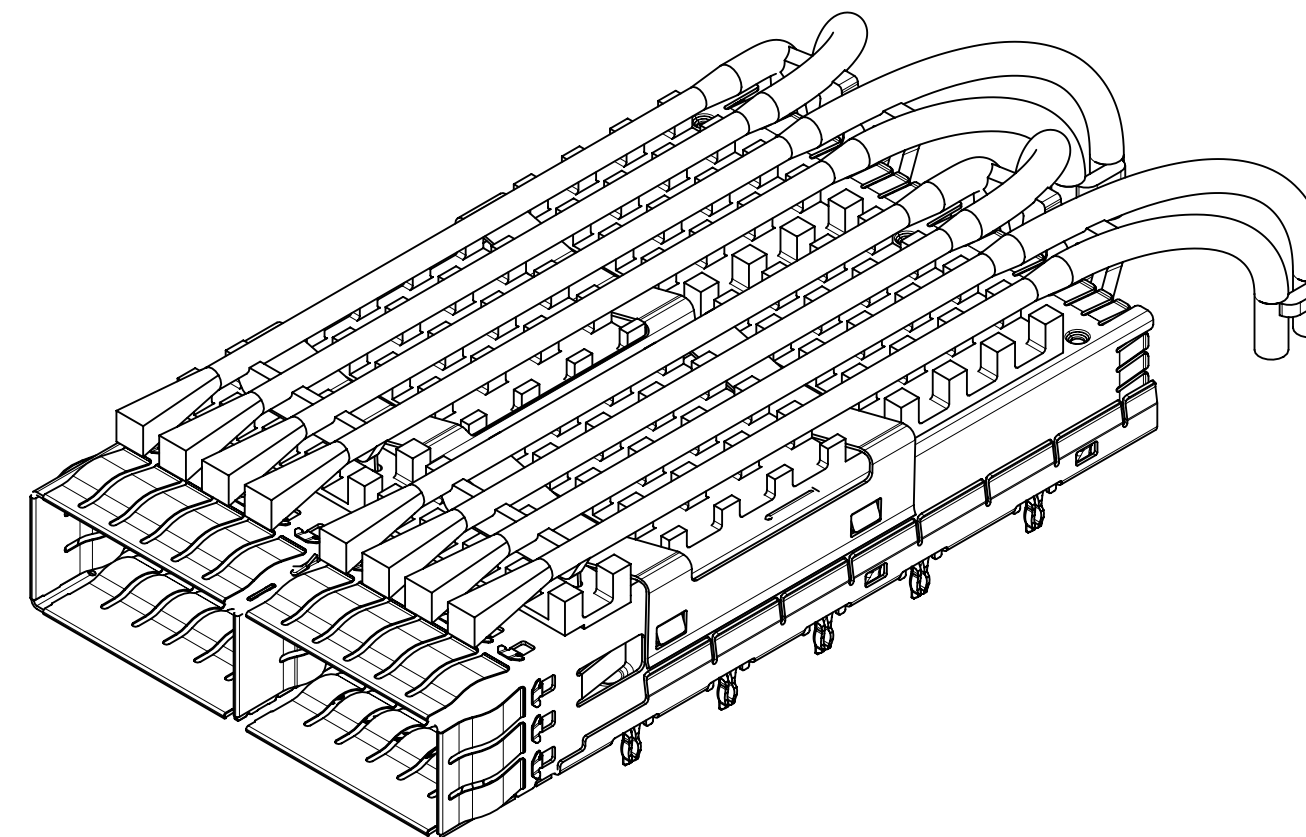
PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111312930	75	150	OBSOLETE
1111312931	75	200	OBSOLETE
1111312932	75	300	OBSOLETE
1111312933	75	400	OBSOLETE
1111312934	75	500	OBSOLETE

*SEE SHEET 8 FOR LIGHT PIPE OPTIONS



OPEN TOP WITH HEAT SINK

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111312940	75	150	OBSOLETE
1111312941	75	200	OBSOLETE
1111312942	75	300	OBSOLETE
1111312943	75	400	OBSOLETE
1111312944	75	500	OBSOLETE



OPEN TOP WITH WITH HEAT SINK AND LIGHTPIPE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111312911	75	150	OBSOLETE
1111312912	75	200	OBSOLETE
1111312913	75	300	OBSOLETE
1111312914	75	400	OBSOLETE
1111312915	75	500	OBSOLETE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111313060	75	150
1111313061	75	200
1111313062	75	300
1111313063	75	400
1111313064	75	500
1111313065	75	210

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111312970	75	150
1111312971	75	200
1111312972	75	300
1111312973	75	400
1111312974	75	500

*SEE SHEET 8 FOR LIGHT PIPE OPTIONS

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111312980	75	150
1111312981	75	200
1111312982	75	300
1111312983	75	400
1111312984	75	500

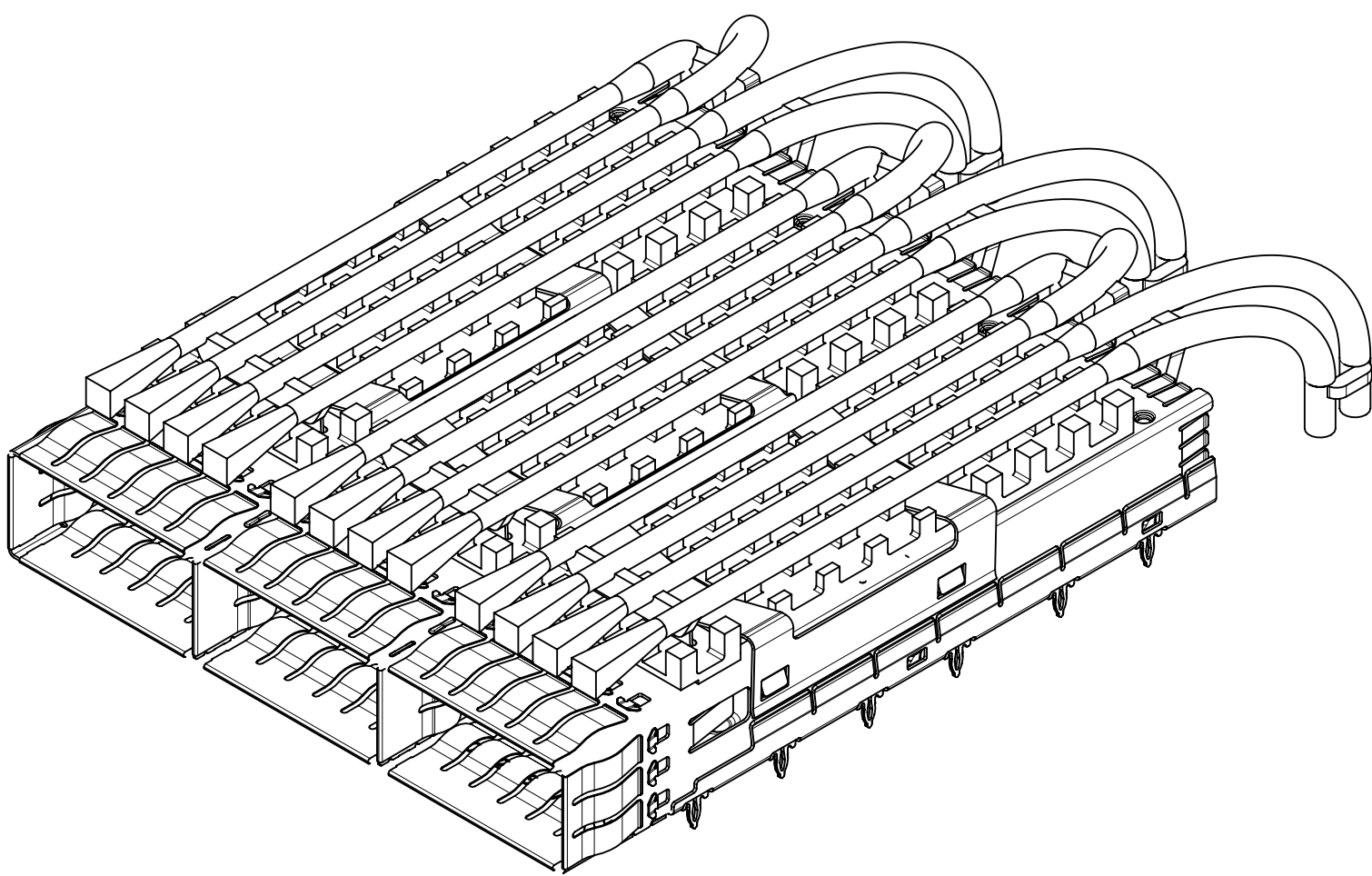
*SEE SHEET 8 FOR HEAT SINK OPTIONS

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111312950	75	150
1111312951	75	200
1111312952	75	300
1111312953	75	400
1111312954	75	500

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]					molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP PRODUCT SALES DRAWING								
	MM		2:1															
	GENERAL TOLERANCES (UNLESS SPECIFIED)																	
	ANGULAR TOL ± 0.5°																	
	4 PLACES		±															
	3 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04					DOCUMENT NUMBER		DOC TYPE		DOC PART		REVISION		
	2 PLACES		±							1111310799		PSD		000		J1		
	1 PLACE		±															
	0 PLACES		±															
DIVISIONAL SYMBOLS	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER			
							D-SIZE		111131				GENERAL MARKET		3 OF 17			

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



OPEN TOP WITH WITH HEAT SINK AND LIGHTPIPE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111313911	75	150	OBSOLETE
1111313912	75	200	OBSOLETE
1111313913	75	300	OBSOLETE
1111313914	75	400	OBSOLETE
1111313915	75	500	OBSOLETE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111313950	75	150
1111313951	75	200
1111313952	75	300
1111313953	75	400
1111313954	75	500

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

FUNCTIONAL SYMBOLS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
F = 0		DIMENSION UNITS MM		SCALE 2:1		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]				molex							
E = 0		GENERAL TOLERANCES (UNLESS SPECIFIED)															
P = 0		ANGULAR TOL ± 0.5°															
DIVISIONAL SYMBOLS		4 PLACES		±						PRODUCT SALES DRAWING							
		3 PLACES		±										DOCUMENT NUMBER 1111310799			
		2 PLACES		±													
		1 PLACE		±		DOC PART 000											
0 PLACES		±		REVISION J1													
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION								DRAWING D-SIZE		SERIES 111131		MATERIAL NUMBER		CUSTOMER GENERAL MARKET	
		Third Angle Projection Symbol															

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



CLOSE TOP WITH LIGHTPIPE



OPEN TOP WITH HEAT SINK



OPEN TOP WITH HEAT SINK AND LIGHTPIPE



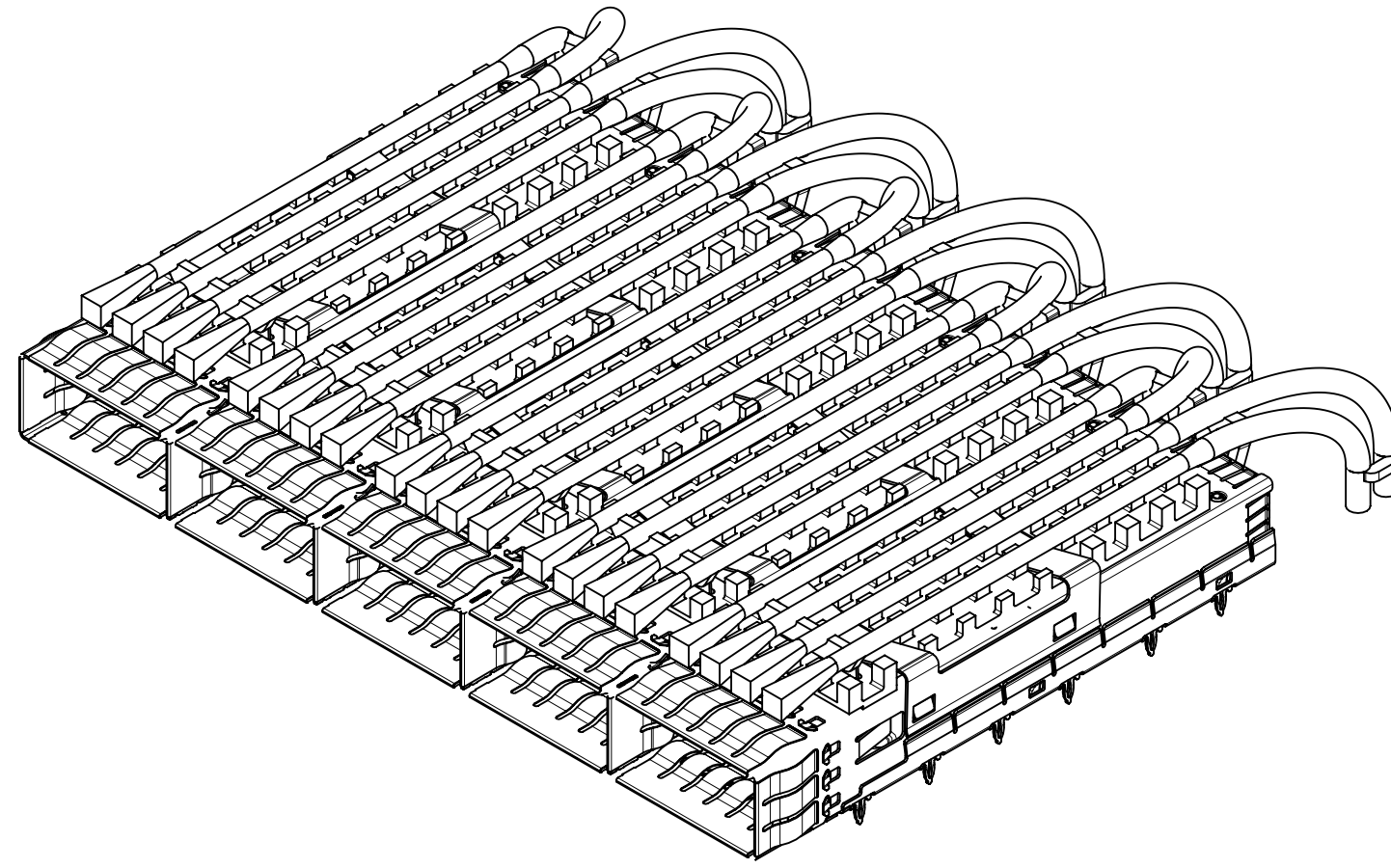
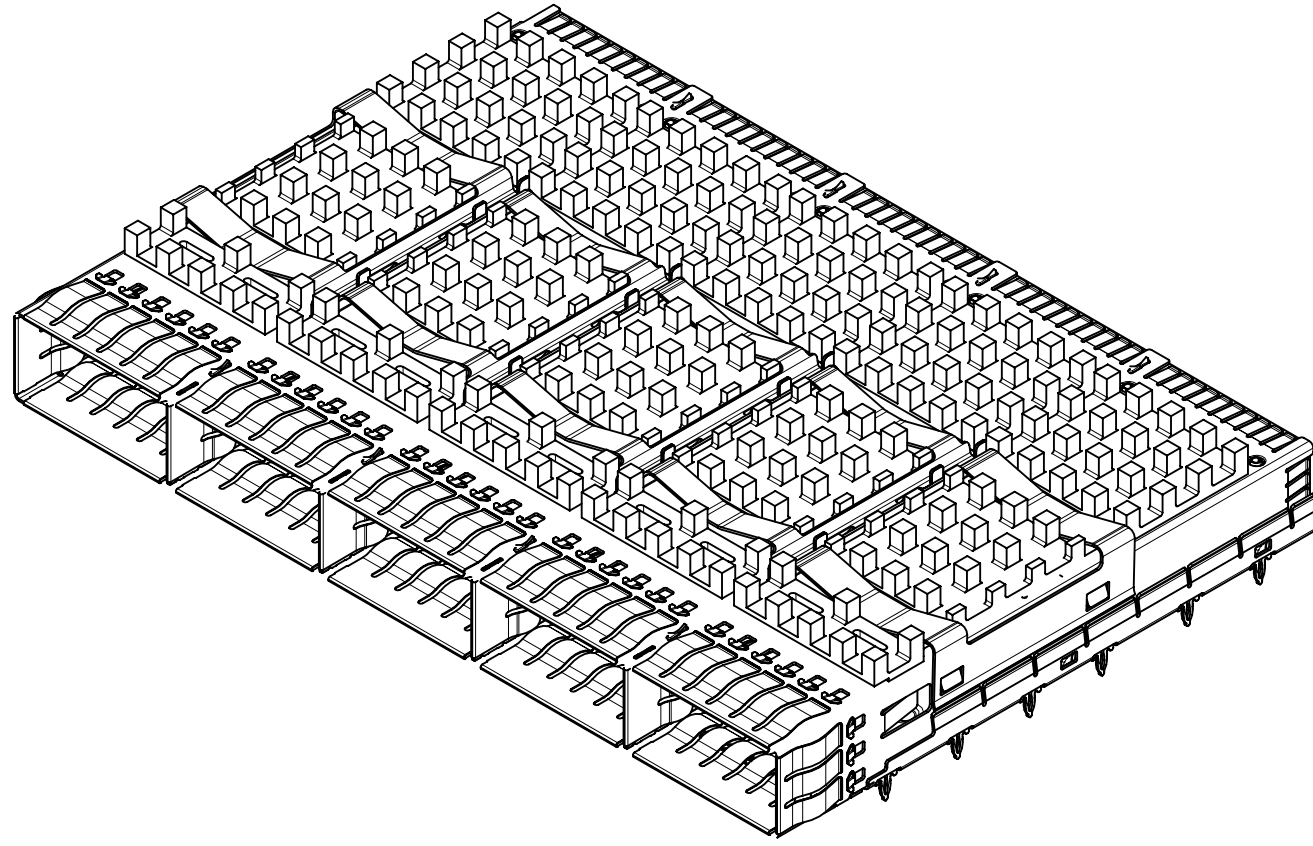
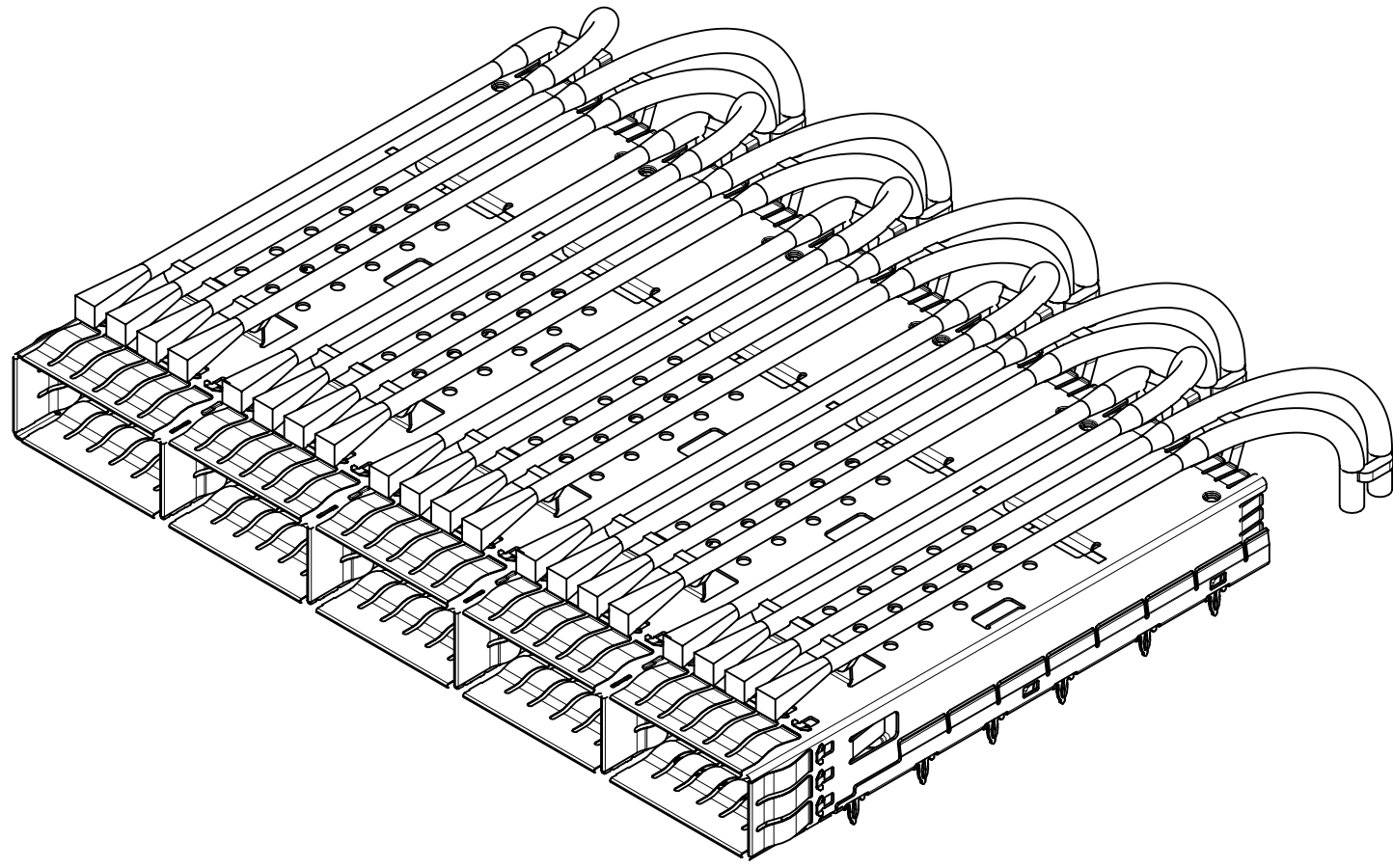
*SEE SHEET 8 FOR LIGHT PIPE OPTIONS

*SEE SHEET 8 FOR HEAT SINK OPTIONS

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex				
	MM		2:1									
	$F_A = 0$		GENERAL TOLERANCES (UNLESS SPECIFIED)					ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP				
$F_C = 0$		ANGULAR TOL ± 0.5°										
$F_D = 0$		4 PLACES		±								
DIVISIONAL SYMBOLS	3 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04						PRODUCT SALES DRAWING	
	2 PLACES		±					DOCUMENT NUMBER		DOC TYPE		
	1 PLACE		±					1111310799		PSD	000	J1
	0 PLACES		±									
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER	SHEET NUMBER	
						D-SIZE	111131			GENERAL MARKET	5 OF 17	

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



OPEN TOP WITH HEAT SINK AND LIGHTPIPE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111315911	75	150	OBSOLETE
1111315912	75	200	OBSOLETE
1111315913	75	300	OBSOLETE
1111315914	75	400	OBSOLETE
1111315915	75	500	OBSOLETE

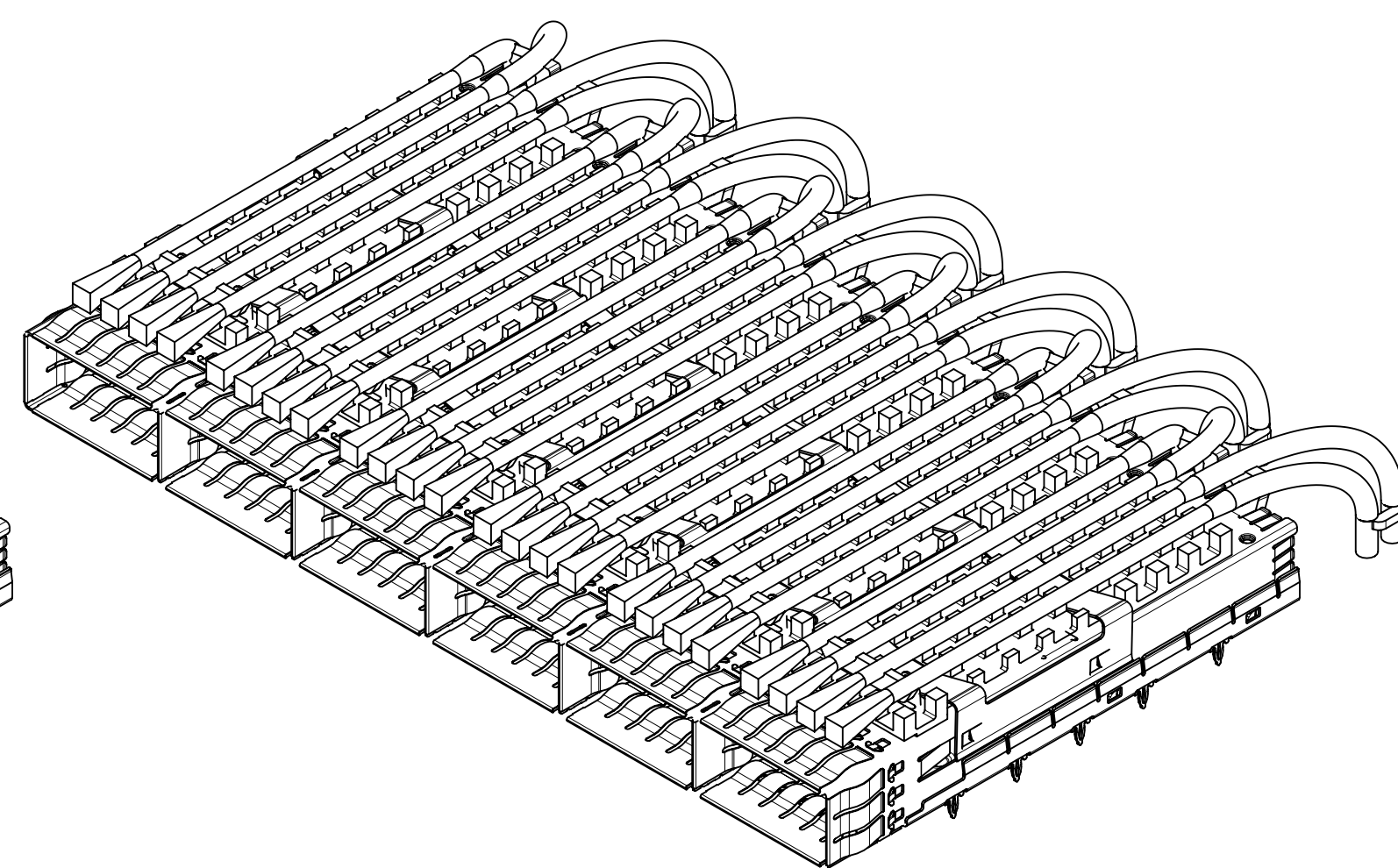
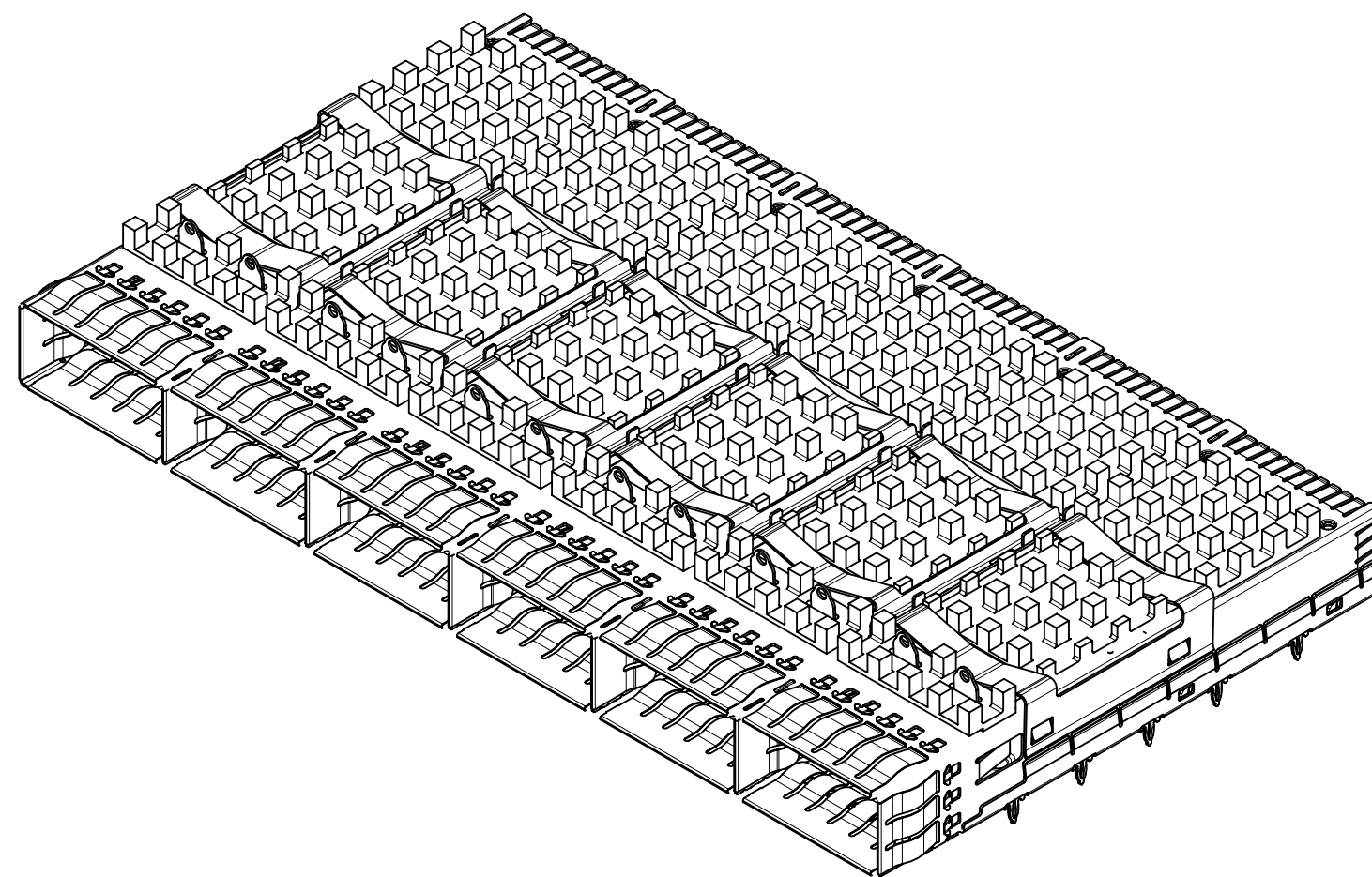
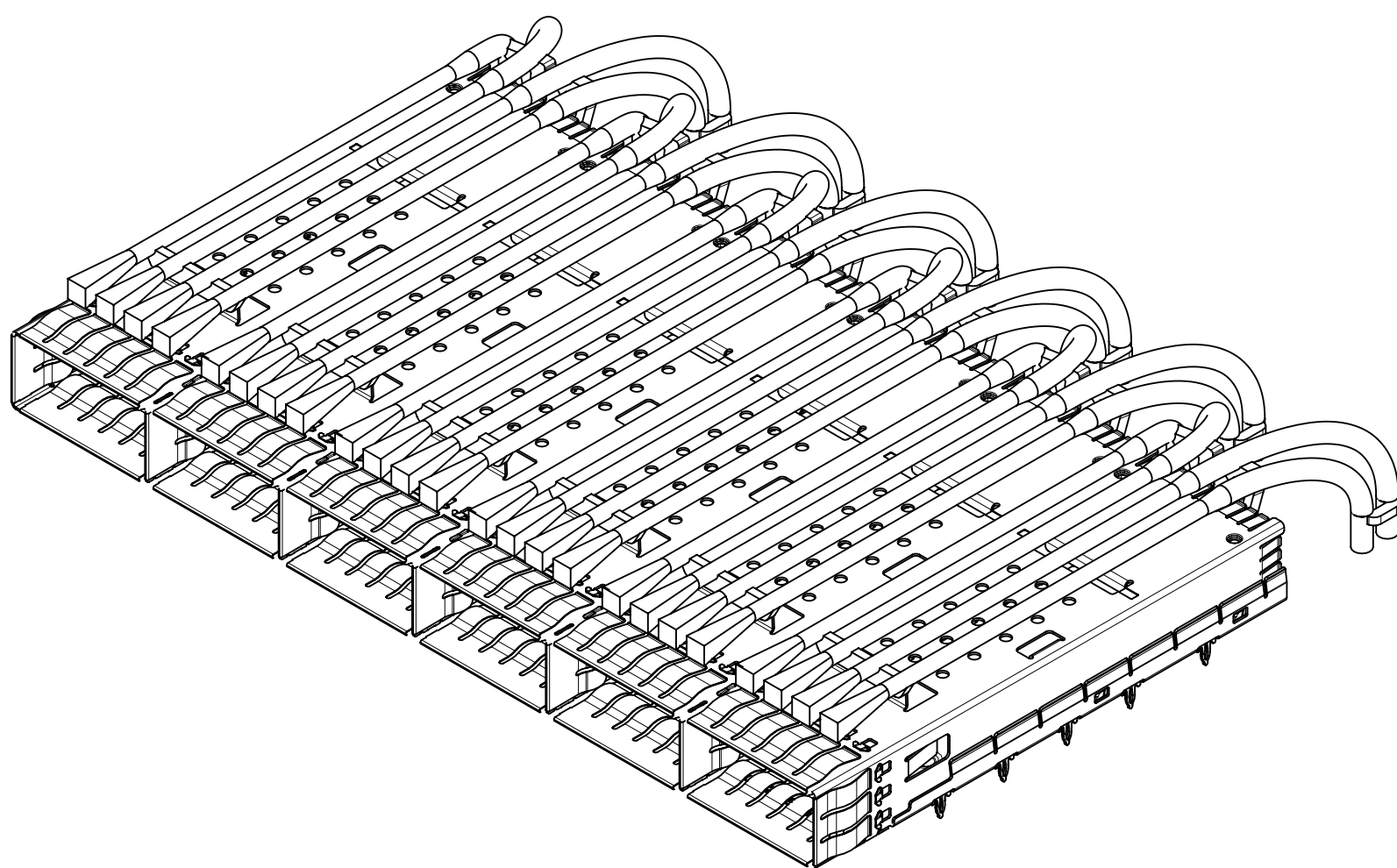
PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111315970	75	150
1111315971	75	200
1111315972	75	300
1111315973	75	400
1111315974	75	500

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111315950	75	150
1111315951	75	200
1111315952	75	300
1111315953	75	400
1111315954	75	500

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex				
	MM		2:1									
	$\nabla_{FA} = 0$		GENERAL TOLERANCES (UNLESS SPECIFIED)					ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP				
$\nabla_{FE} = 0$		ANGULAR TOL ± 0.5°										
$\nabla_{FD} = 0$		4 PLACES ±										
DIVISIONAL SYMBOLS		3 PLACES ±										
		2 PLACES ±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04			PRODUCT SALES DRAWING					
		1 PLACE ±										
		0 PLACES ±					DOCUMENT NUMBER 1111310799			DOC TYPE PSD	DOC PART 000	REVISION J1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER		
		 		D-SIZE	111131			GENERAL MARKET		6 OF 17		

NOTE: ALL LENGTHS $\pm 5.0\text{mm}$



OPEN TOP WITH HEAT SINK AND LIGHTPIPE

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 1.0) HIGH SPEED LENGTH (MM)	REMARK
1111316911	75	150	OBSOLETE
1111316912	75	200	OBSOLETE
1111316913	75	300	OBSOLETE
1111316914	75	400	OBSOLETE
1111316915	75	500	OBSOLETE

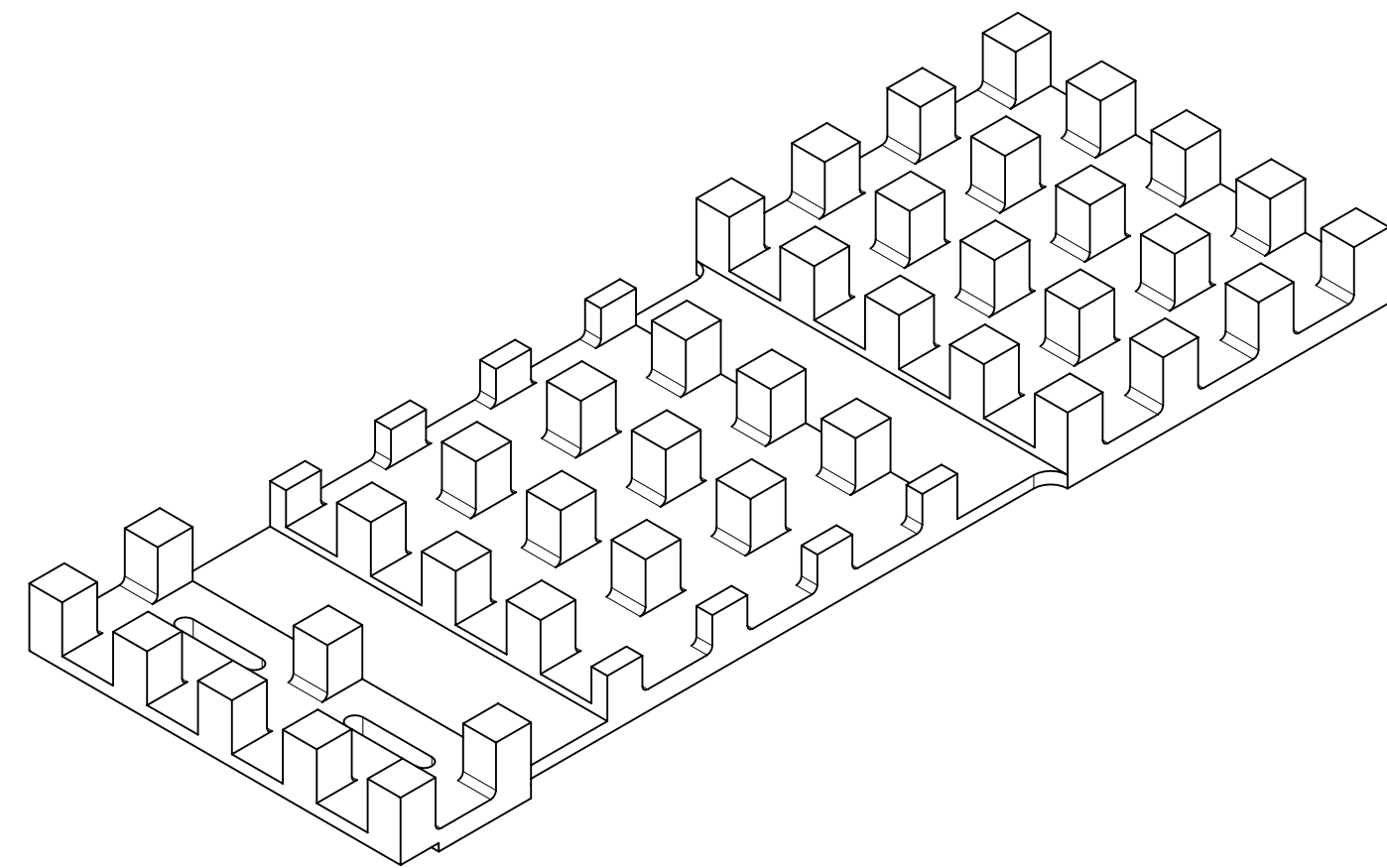
PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111316970	75	150
1111316971	75	200
1111316972	75	300
1111316973	75	400
1111316974	75	500

*SEE SHEET 8 FOR HEAT SINK AND LIGHT PIPE OPTIONS

PART NUMBER	PICO-CLASP LOW SPEED LENGTH (MM)	NEARSTACK (GEN 2.0) HIGH SPEED LENGTH (MM)
1111316950	75	150
1111316951	75	200
1111316952	75	300
1111316953	75	400
1111316954	75	500

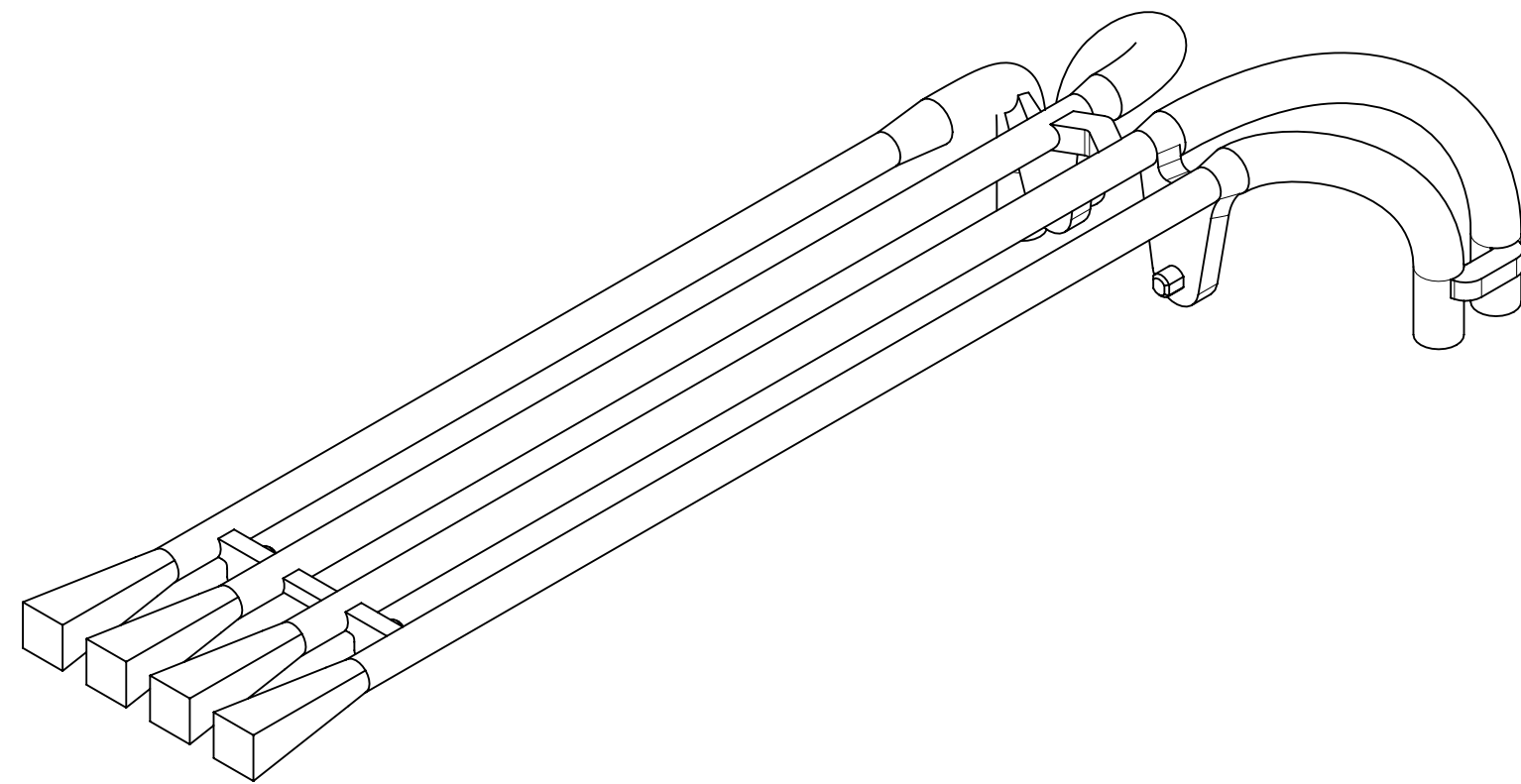
FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
F_A = 0	DIMENSION UNITS		SCALE	CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]				molex				
F_C = 0	MM		2:1	GENERAL TOLERANCES (UNLESS SPECIFIED)				ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP				
F_P = 0	ANGULAR TOL		± 0.5°									
DIVISIONAL SYMBOLS	4 PLACES		±	STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04				PRODUCT SALES DRAWING				
	3 PLACES		±									DOCUMENT NUMBER
	2 PLACES		±					1111310799		PSD	000	J1
	1 PLACE		±									
	0 PLACES		±									
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER		
				D-SIZE	111131			GENERAL MARKET		7 OF 17		

STANDARD HEAT SINK
USED ON ASSEMBLIES SHOWN
IN THIS DRAWING



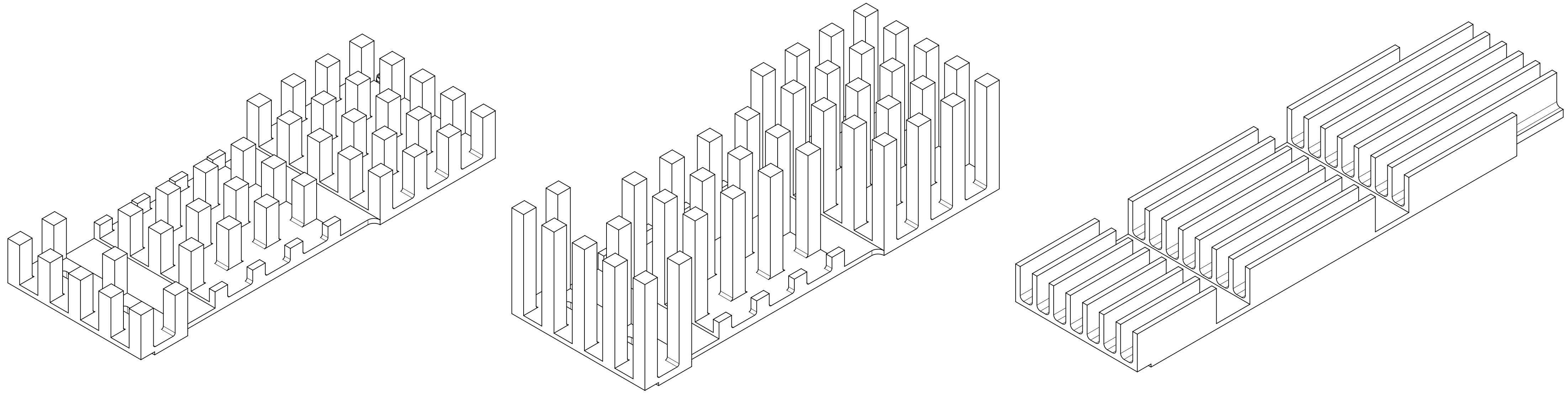
HEAT SINK PIN TYPE
HEIGHT = 3.1MM
(PCI)

STANDARD LIGHT PIPE
USED ON ASSEMBLIES SHOWN
IN THIS DRAWING



LIGHT PIPE
4 CHANNEL

HEAT SINK OPTIONS

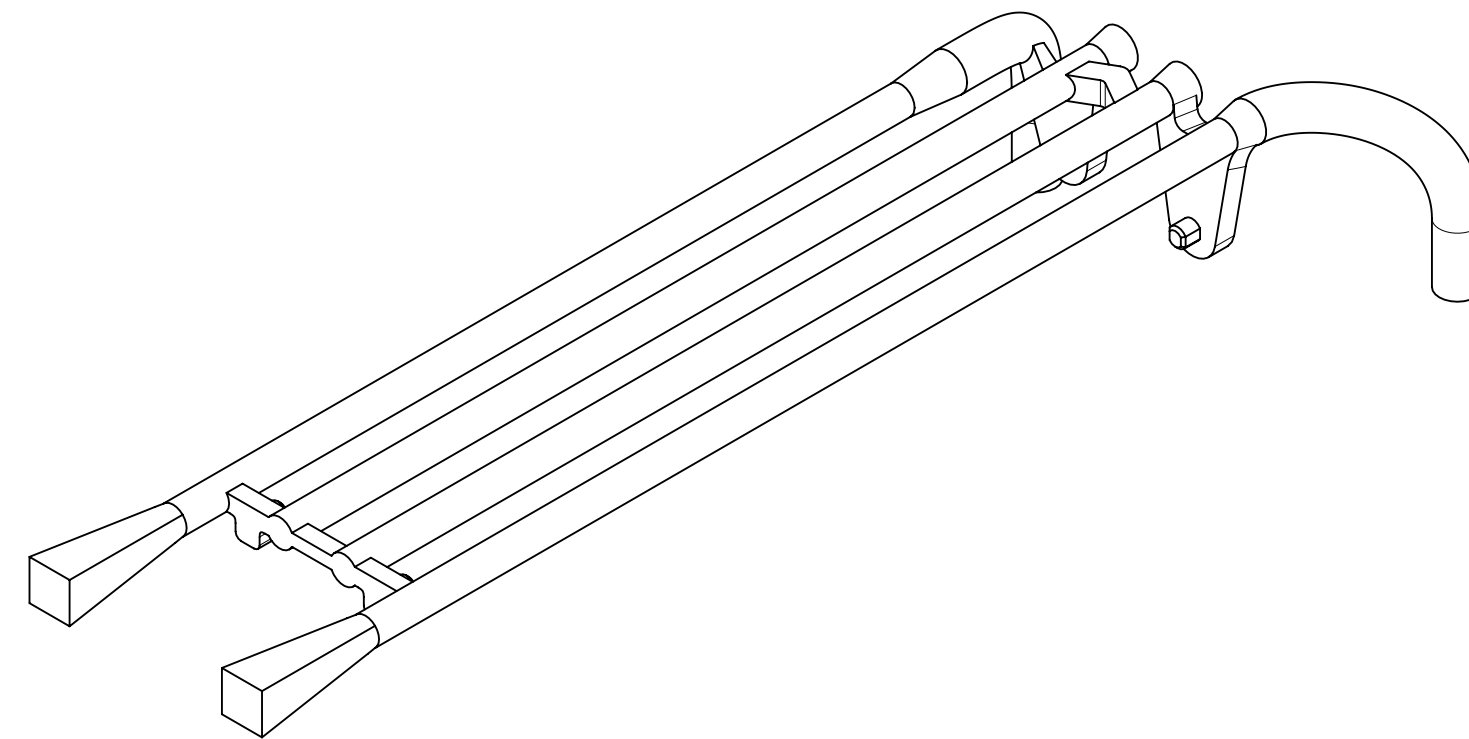


HEAT SINK PIN TYPE
HEIGHT = 5.4MM
(SAN)

HEAT SINK PIN TYPE
HEIGHT = 12.4MM
(NET)

HEAT SINK FIN TYPE
HEIGHT = 3.7MM

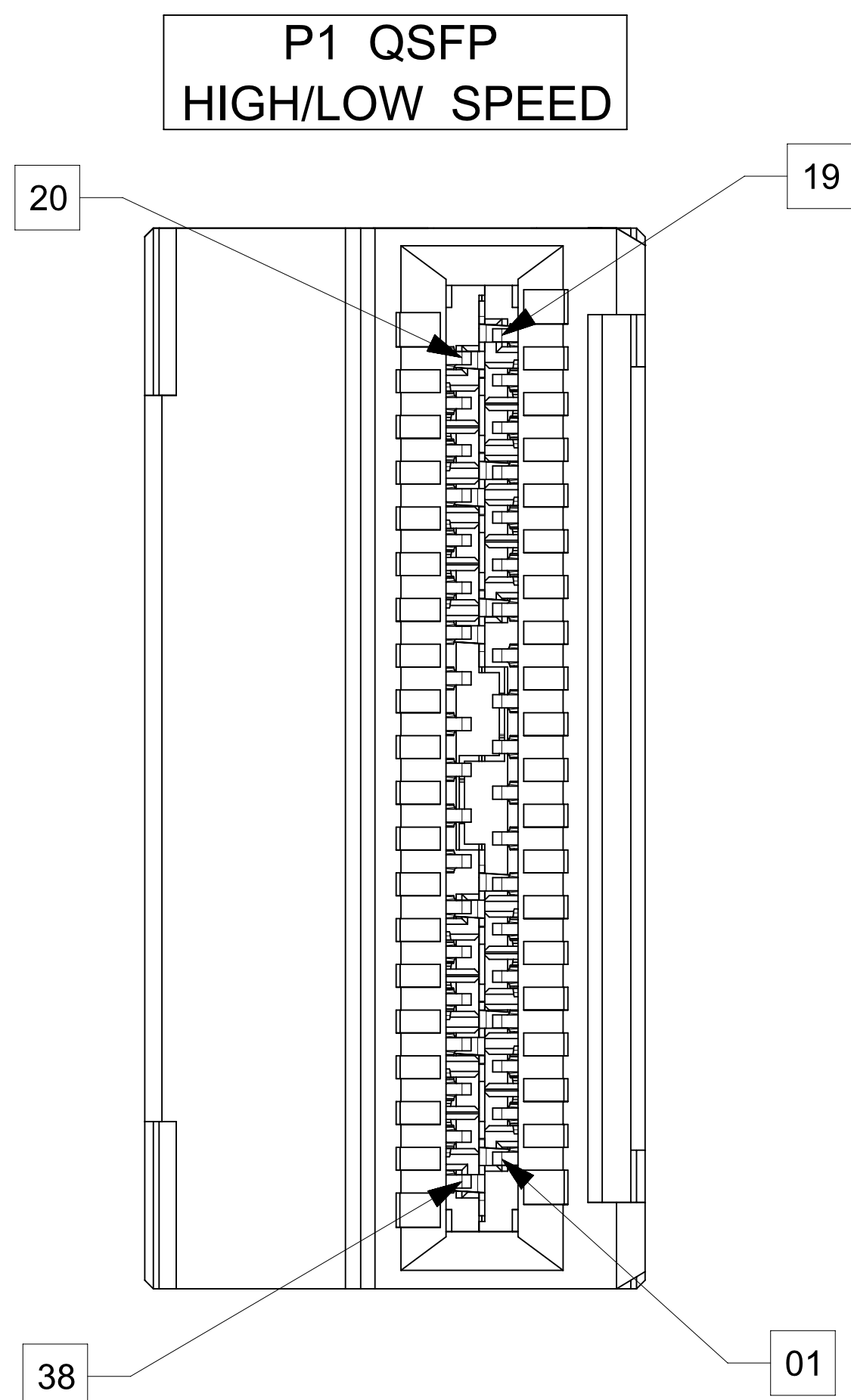
LIGHT PIPE OPTIONS



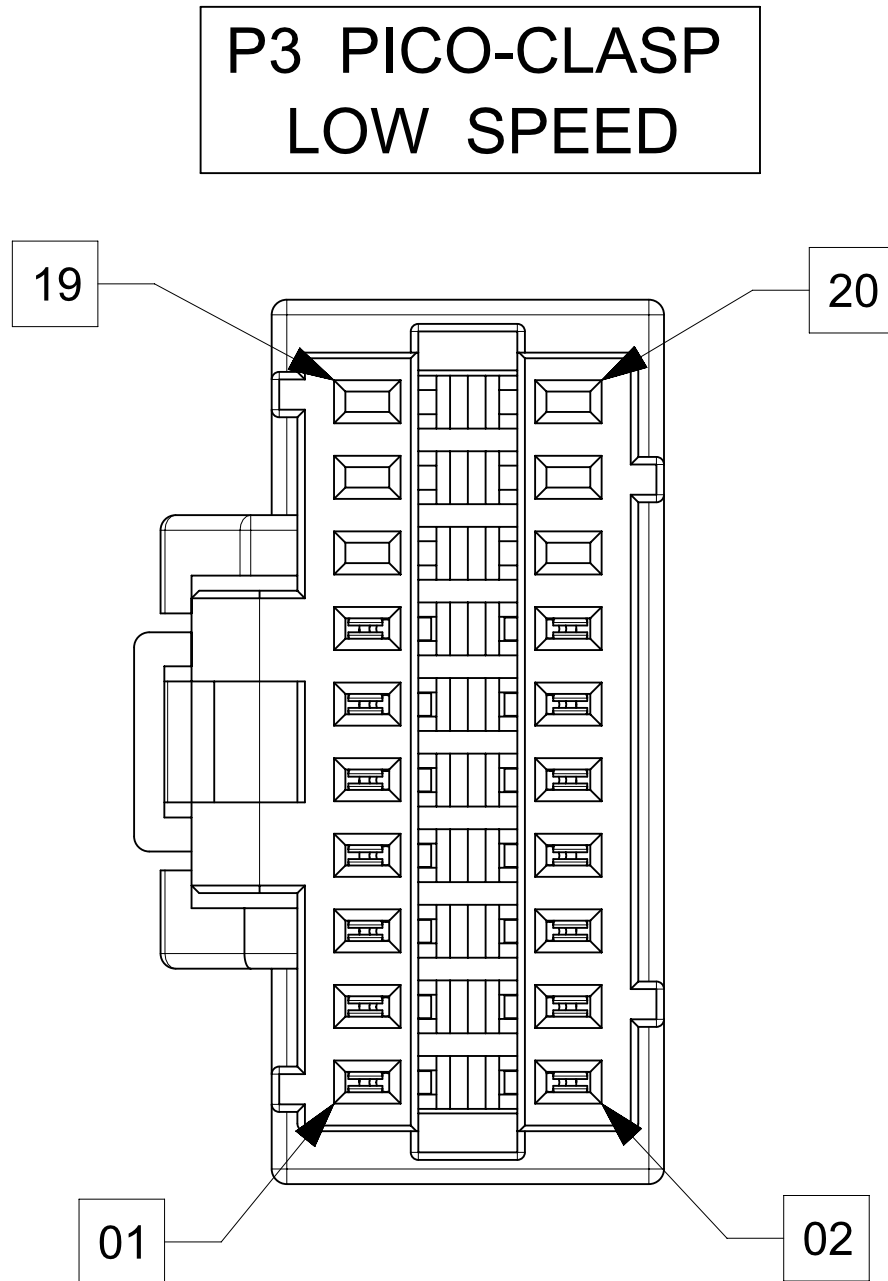
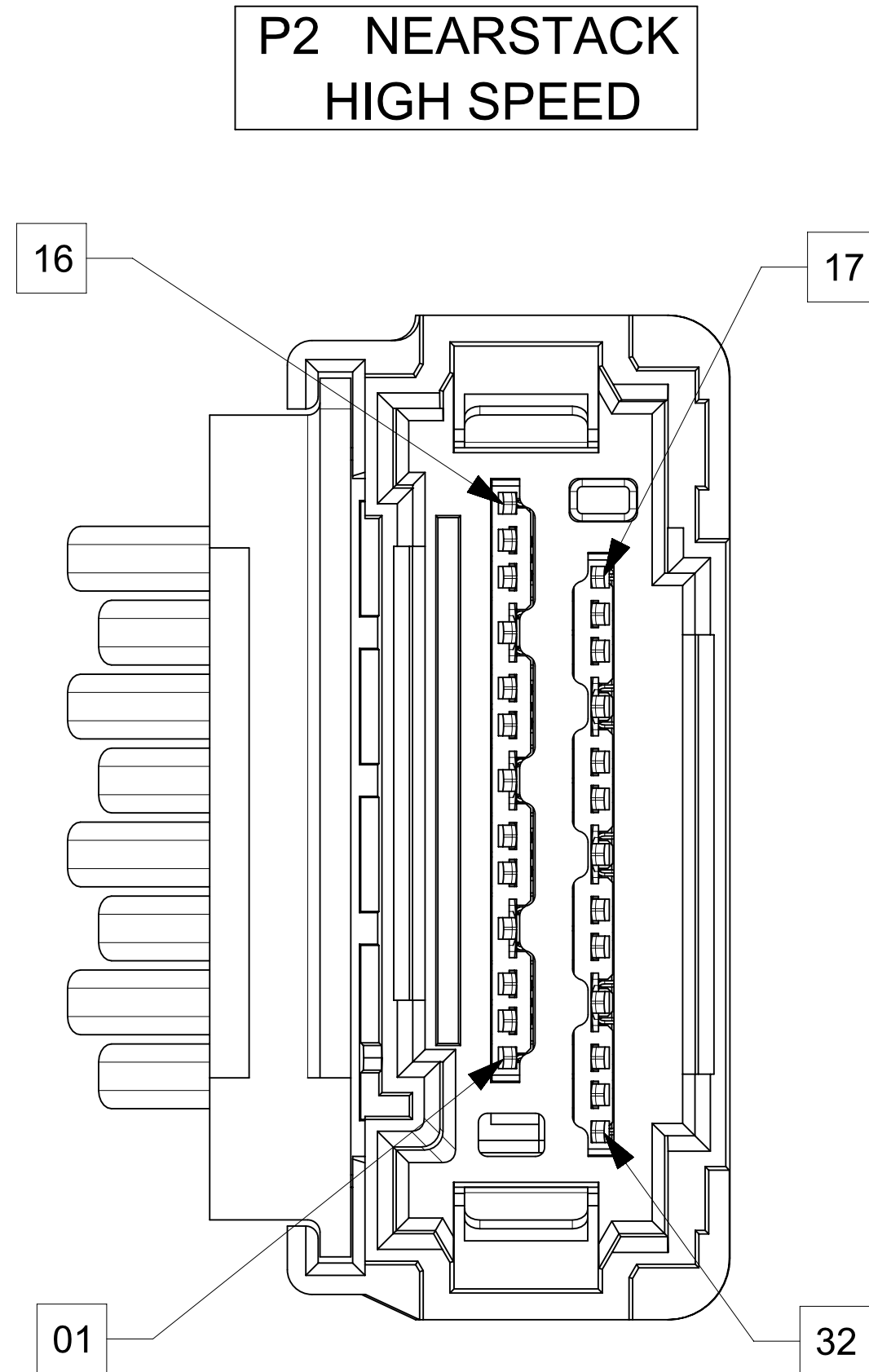
LIGHT PIPE
2 CHANNEL

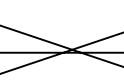
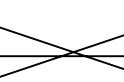
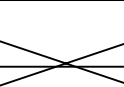
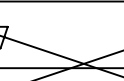
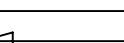
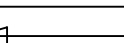
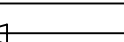
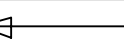
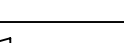
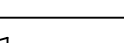
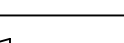
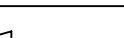
CONTACT MOLEX FOR BiPASS ASSEMBLY PART NUMBER AND AVAILABILITY

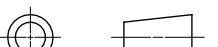
FUNCTIONAL SYMBOLS F_A = 0 F_C = 0 F_P = 0 DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]				molex					
	MM		4:1											
	GENERAL TOLERANCES (UNLESS SPECIFIED)													
	ANGULAR TOL ± 0.5°													
	4 PLACES		±											
	3 PLACES		±											
	2 PLACES		±											
	1 PLACE		±											
	0 PLACES		±											
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER		
				D-SIZE		111131				GENERAL MARKET		8 OF 17		



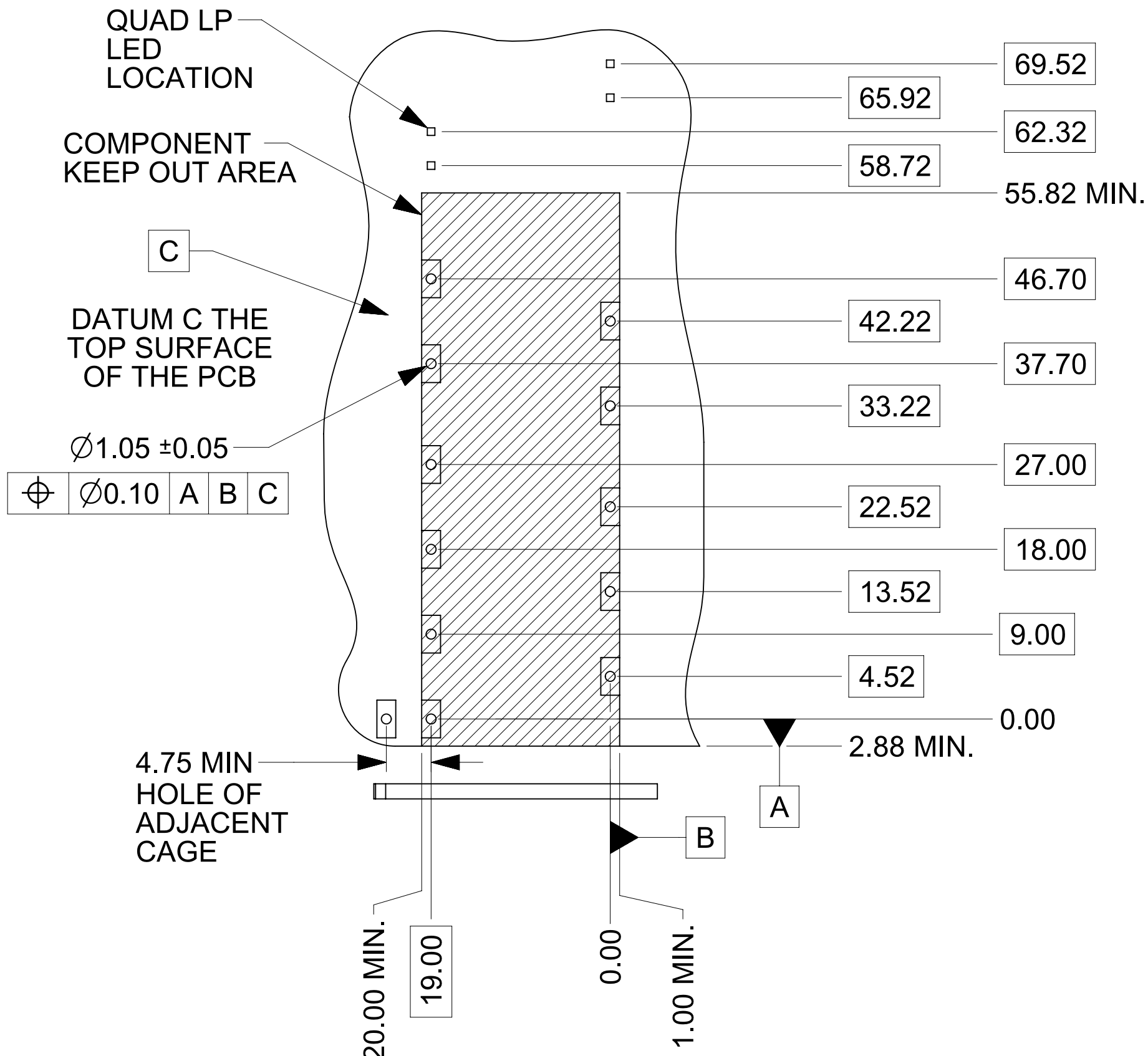
LOW SPEED SIGNALS		
P1		P3
PIN	SIGNAL	PIN
	NC	20
	NC	18
	NC	16
32, 35, 38	GND	14
08	ModSelL	12
09	ResetL	10
10	VccRx	08
11	SCL	06
12	SDA	04
13, 16, 19	GND	02
20, 23, 26	GND	01
27	ModPrsL	03
28	IntL	05
29	VccTx	07
30	Vcc1	09
31	LPMODE	11
1, 4, 7	GND	13
	NC	15
	NC	17
	NC	19



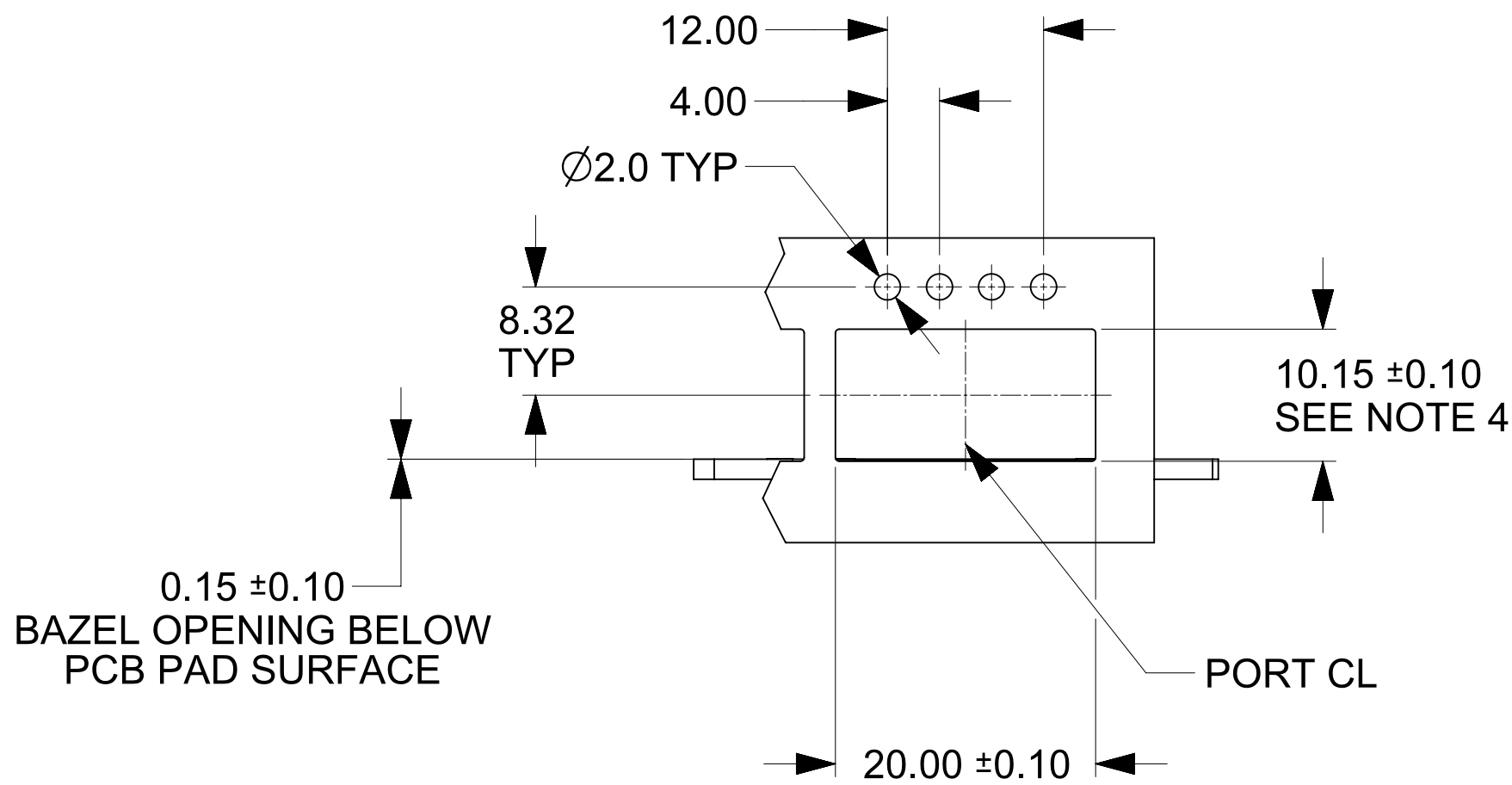
P1 END zQSFP			P2 END NEARSTACK	
PIN	SIGNAL		PIN	SIGNAL
01	GND (TX)		01	GND
02	TX2n		02	TX2p
03	TX2p		03	TX2n
04	GND (TX)		04, 05	GND
05	TX4n		06	TX4p
06	TX4p		07	TX4n
07	GND (TX)		08	GND
13	GND (RX)		09	GND
14	RX3p		10	RX3n
15	RX3n		11	RX3p
16	GND (RX)		12, 13	GND
17	RX1p		14	RX1n
18	RX1n		15	RX1p
19	GND (RX)		16	GND
20	GND (RX)		17	GND
21	RX2n		18	RX2n
22	RX2p		19	RX2p
23	GND (RX)		20, 21	GND
24	RX4n		22	RX4n
25	RX4p		23	RX4p
26	GND (RX)		24	GND
32	GND (TX)		25	GND
33	TX3p		26	TX3p
34	TX3n		27	TX3n
35	GND (TX)		28, 29	GND
36	TX1p		30	TX1p
37	TX1n		31	TX1n
38	GND (TX)		32	GND

FUNCTIONAL SYMBOLS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
$\frac{F}{A} = 0$ $\frac{F}{E} = 0$ $\frac{F}{P} = 0$		DIMENSION UNITS MM		SCALE 10:1		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]							
GENERAL TOLERANCES (UNLESS SPECIFIED)		ANGULAR TOL ± 0.5°		ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP									
4 PLACES ±		3 PLACES ±		PRODUCT SALES DRAWING									
2 PLACES ±		1 PLACE ±		DOCUMENT NUMBER									
0 PLACES ±		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION									
DIVISIONAL SYMBOLS		STATUS: Production		DRWN: Levy Li		2023-11-14		DOC TYPE		DOC PART		REVISION	
		CHK'D: Roy (Yu Da) Liu		2024-03-04		1111310799		PSD		000		J1	
		APPR: Bill (Lie) Chen		2024-03-04									
				DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
		D-SIZE		111131				GENERAL MARKET		9 OF 17			

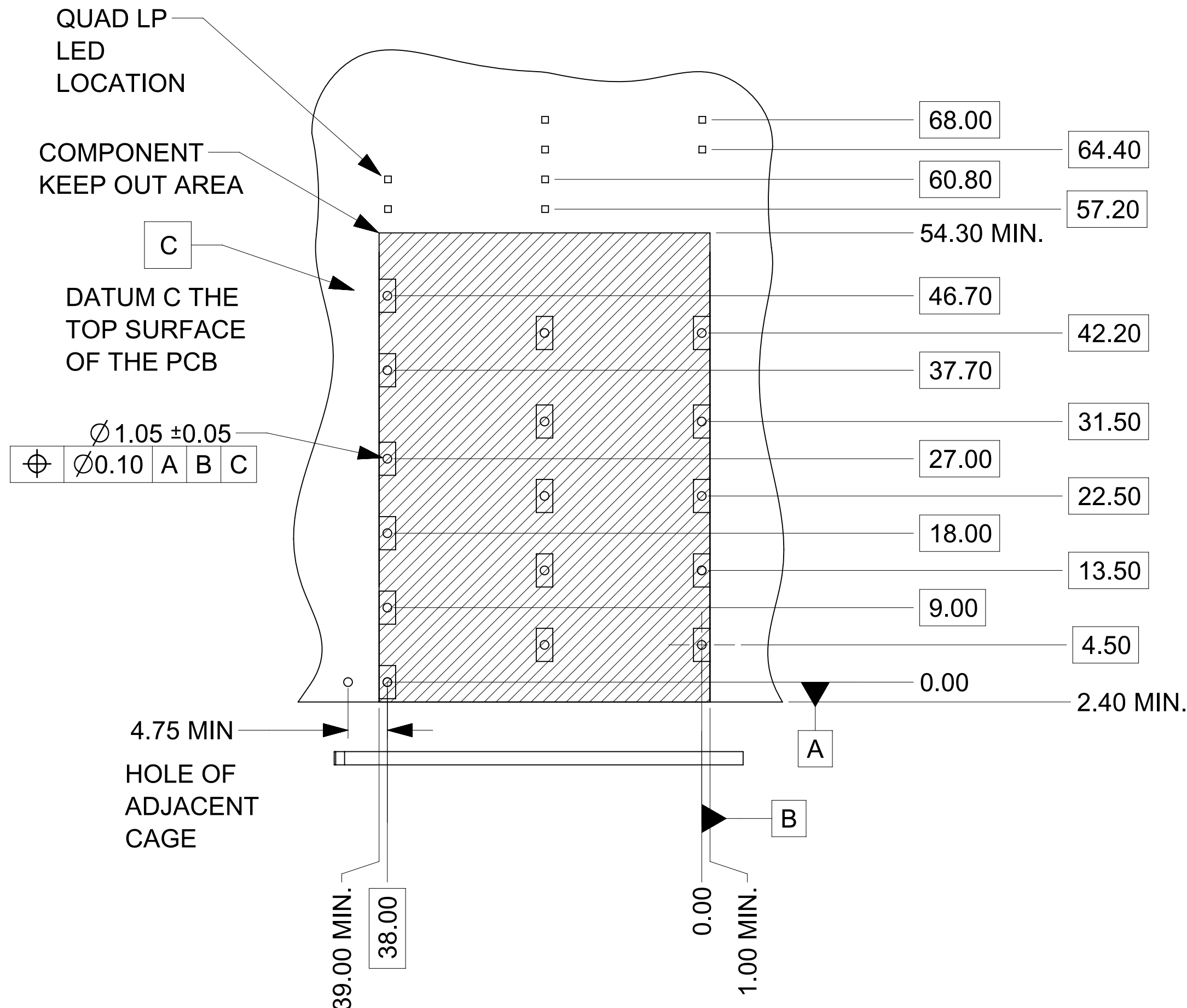
PCB LAYOUT FOR SINGLE SIDED MOUNTING



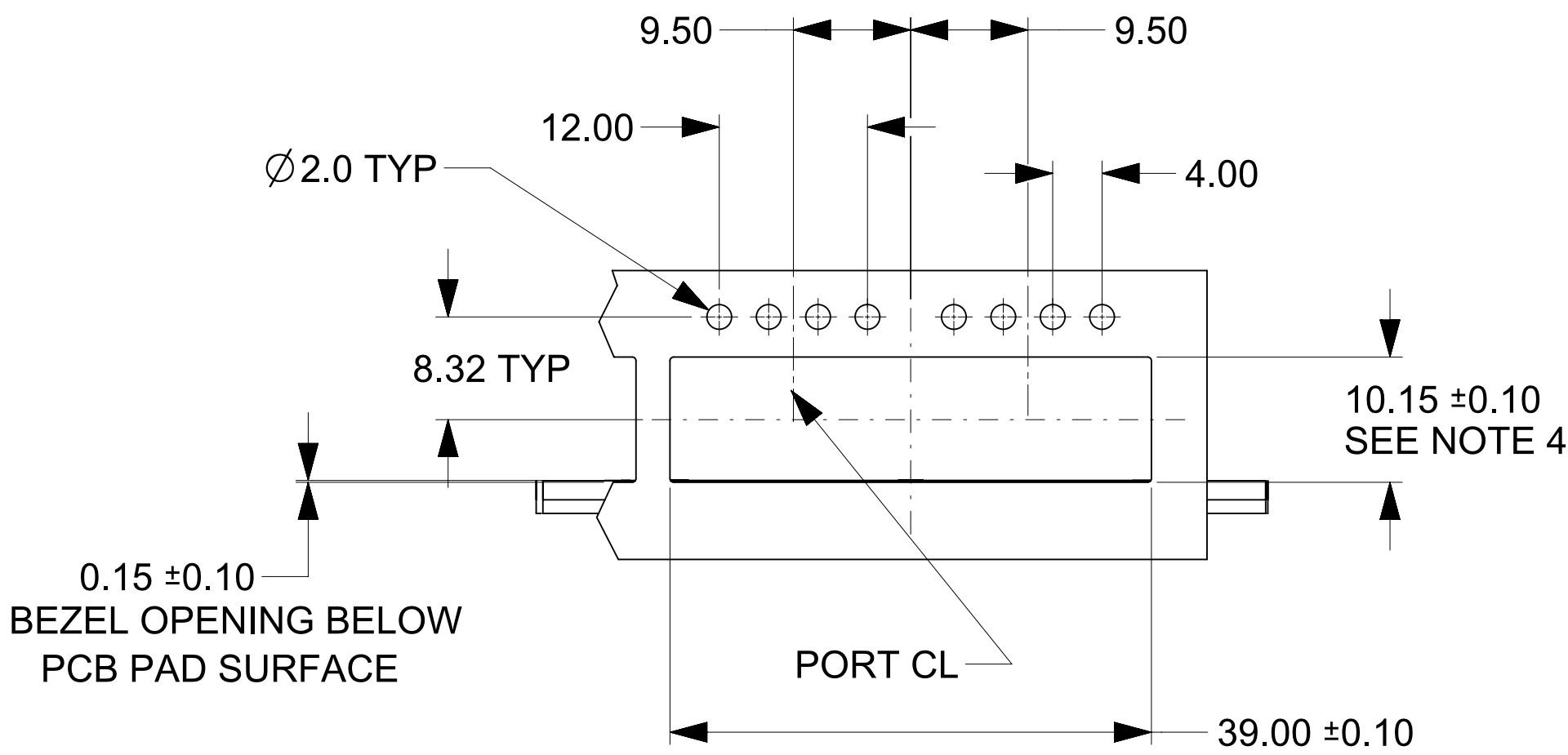
1X1 PCB LAYOUT

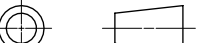


- NOTES:
- PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM - 4.0mm SQUARE)
 - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
 - HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
 - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.

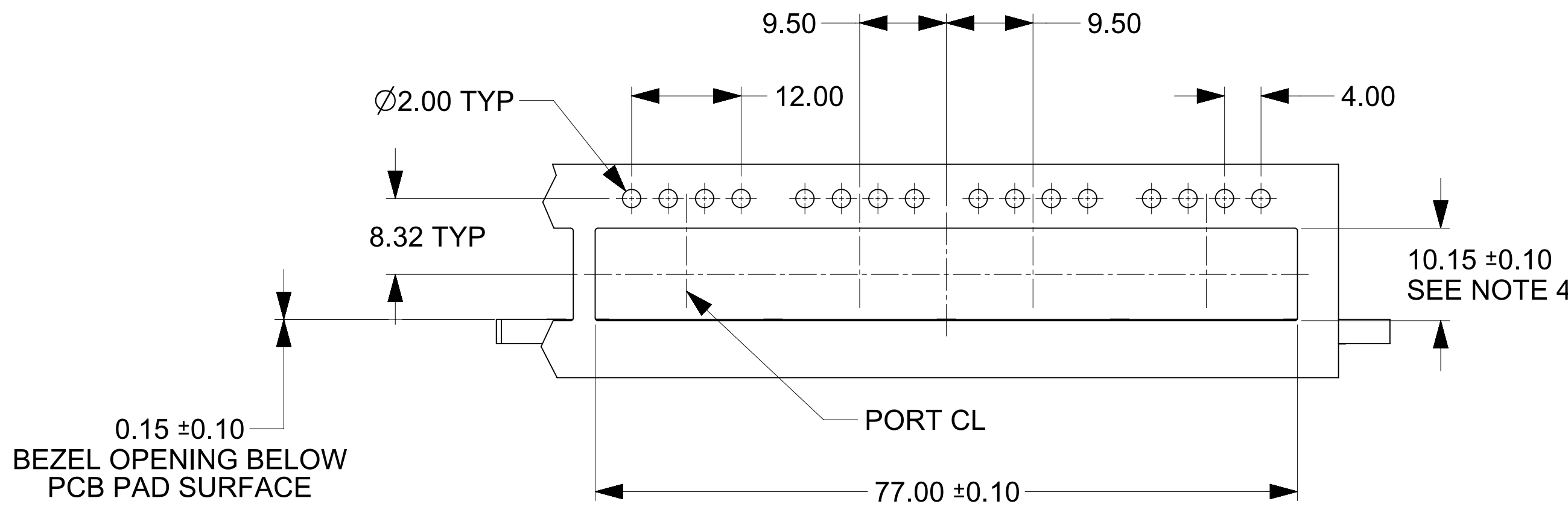
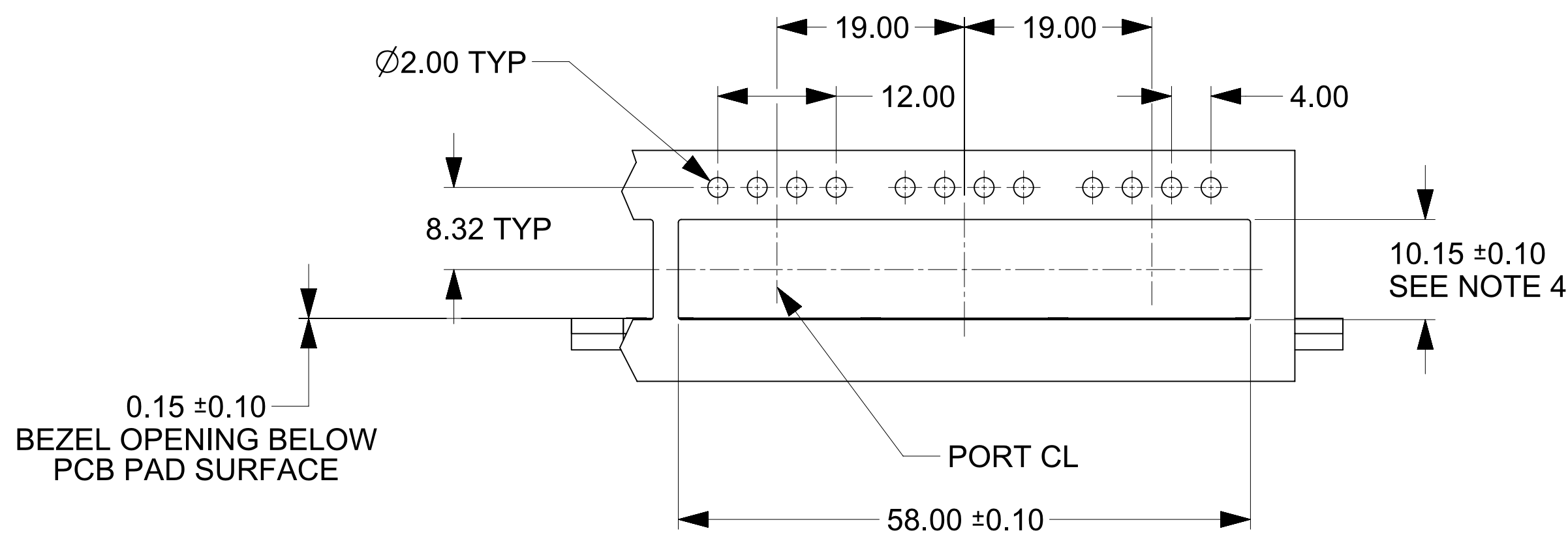
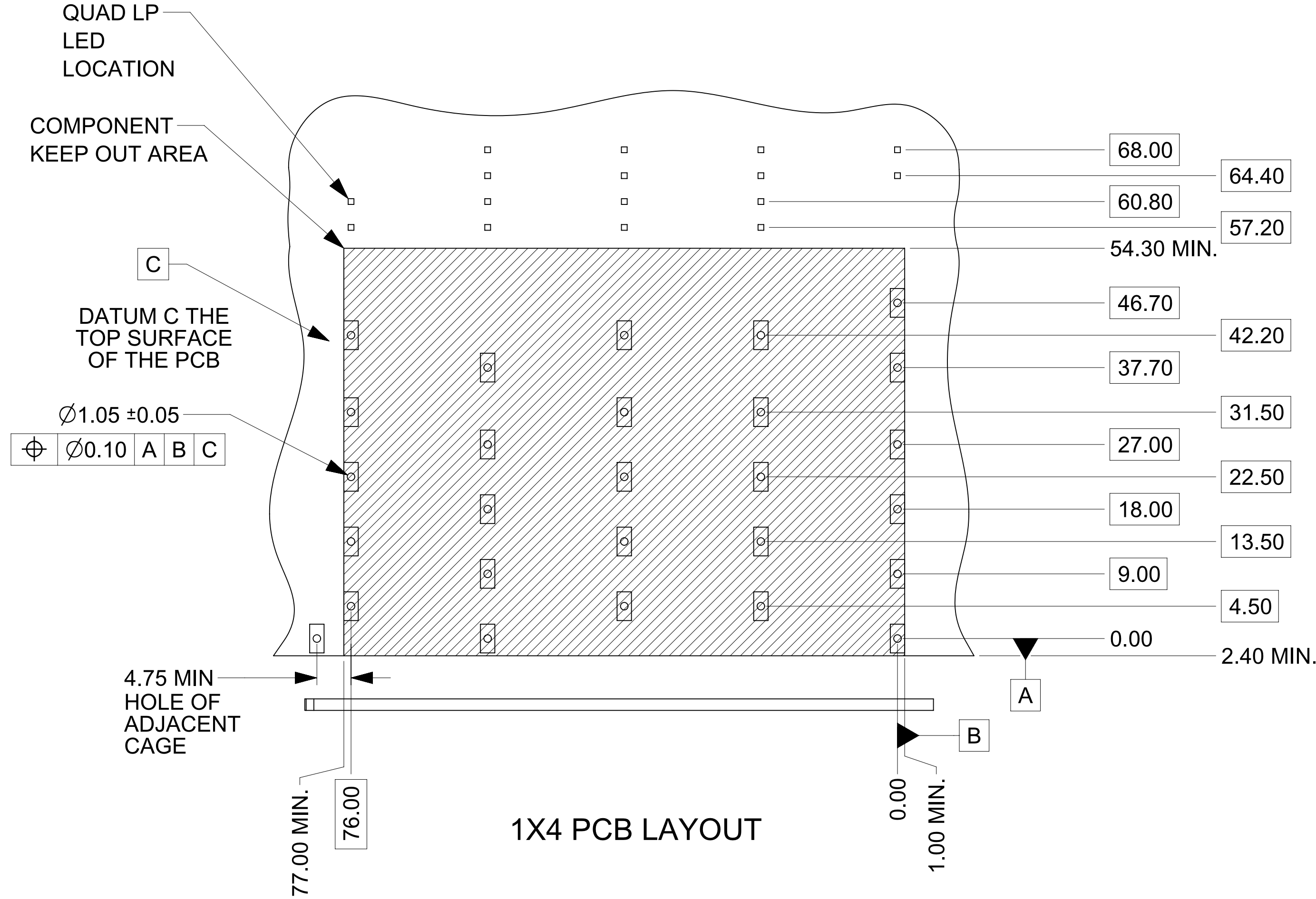
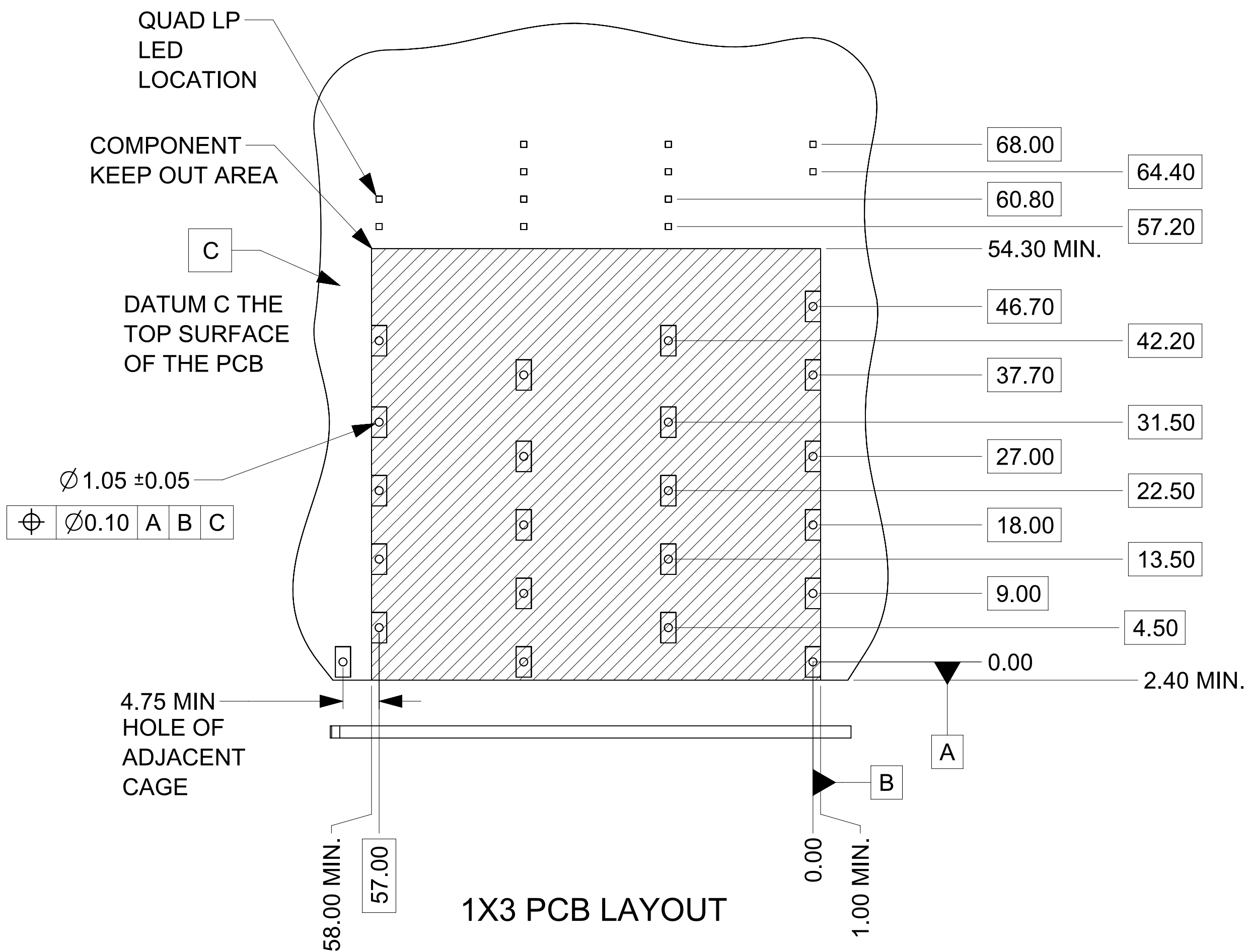


1X2 PCB LAYOUT



FUNCTIONAL SYMBOLS E/A = 0 E/C = 0 E/P = 0 DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP			
	MM		2:1								
	GENERAL TOLERANCES (UNLESS SPECIFIED)										
	ANGULAR TOL		± 0.5°								
	4 PLACES		±		PRODUCT SALES DRAWING						
	3 PLACES		±								
	2 PLACES		±								
	1 PLACE		±								
	0 PLACES		±		DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION		
				1111310799		PSD	000	J1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
		D-SIZE	111131			GENERAL MARKET		10 OF 17			

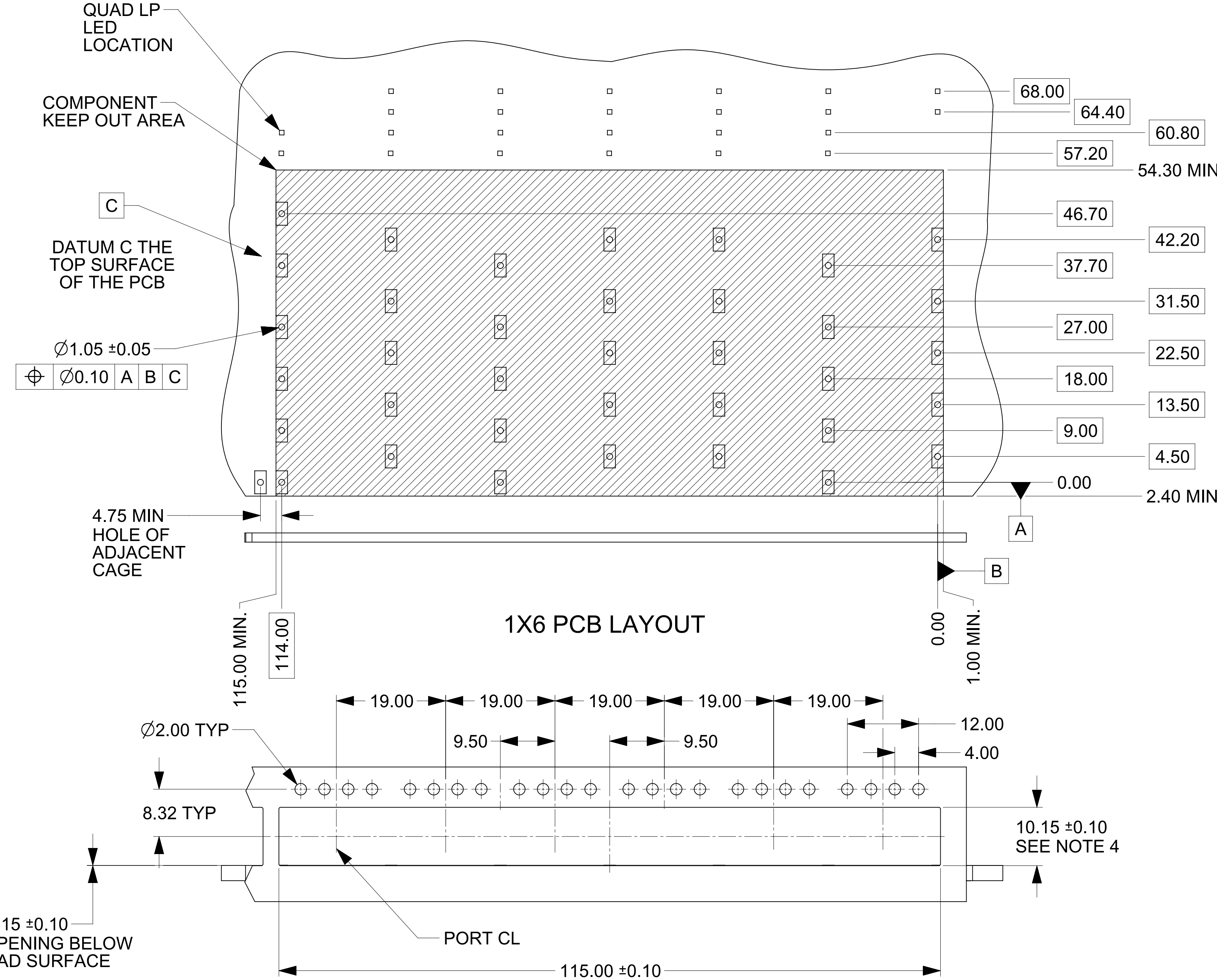
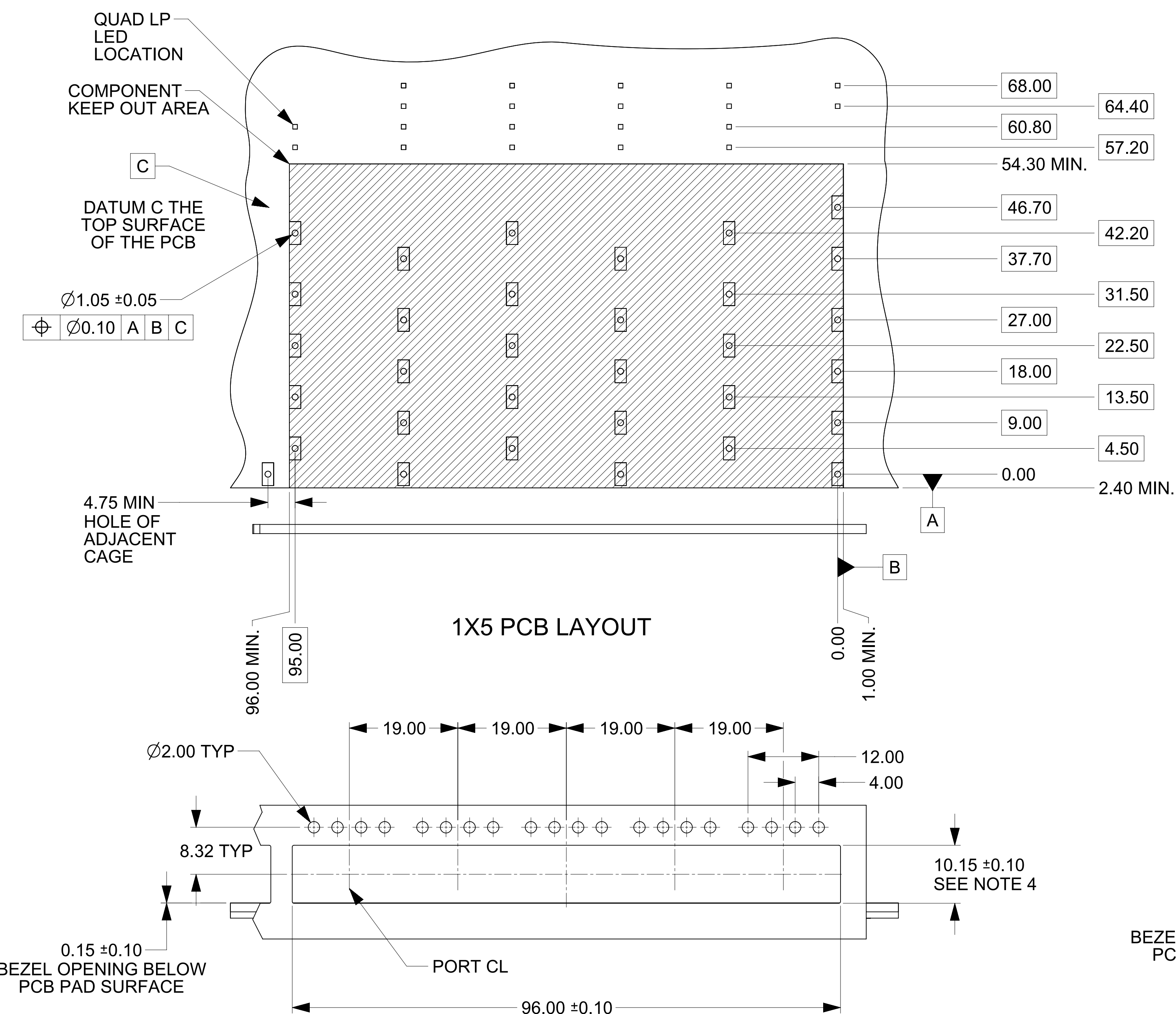
PCB LAYOUT FOR SINGLE SIDED MOUNTING



- NOTES:
- PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM - 4.0MM SQUARE)
 - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
 - HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
 - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.

FUNCTIONAL SYMBOLS F_A = 0 F_C = 0 F_P = 0 DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION														
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]										
	MM		2:1												
	GENERAL TOLERANCES (UNLESS SPECIFIED)				molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP PRODUCT SALES DRAWING DOCUMENT NUMBER 1111310799 DOC TYPE PSD DOC PART 000 REVISION J1										
	ANGULAR TOL ± 0.5°														
	4 PLACES		±												
	3 PLACES		±												
	2 PLACES		±												
	1 PLACE		±												
	0 PLACES		±												
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						D-SIZE		111131				GENERAL MARKET		11 OF 17	

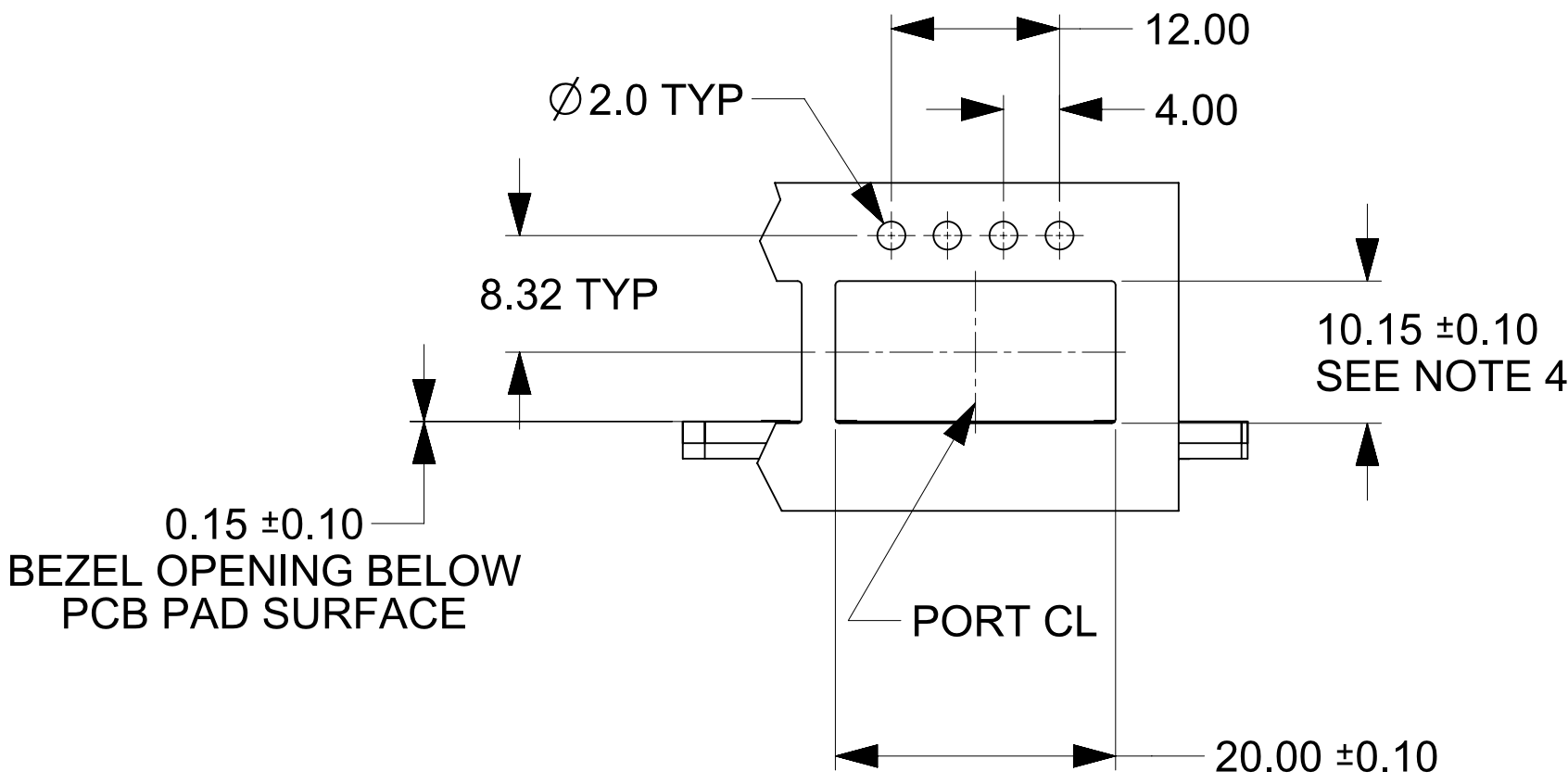
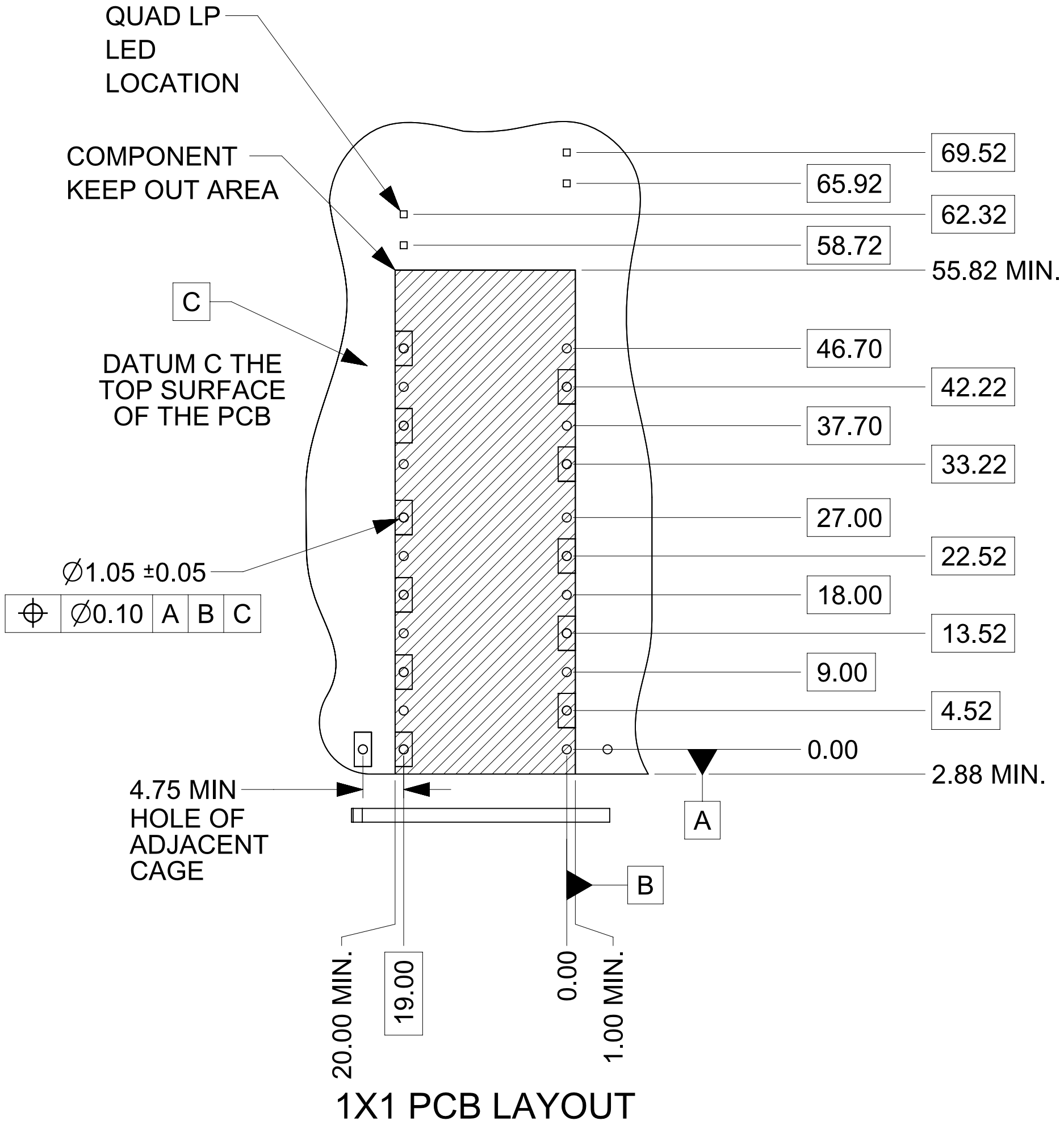
PCB LAYOUT FOR SINGLE SIDED MOUNTING



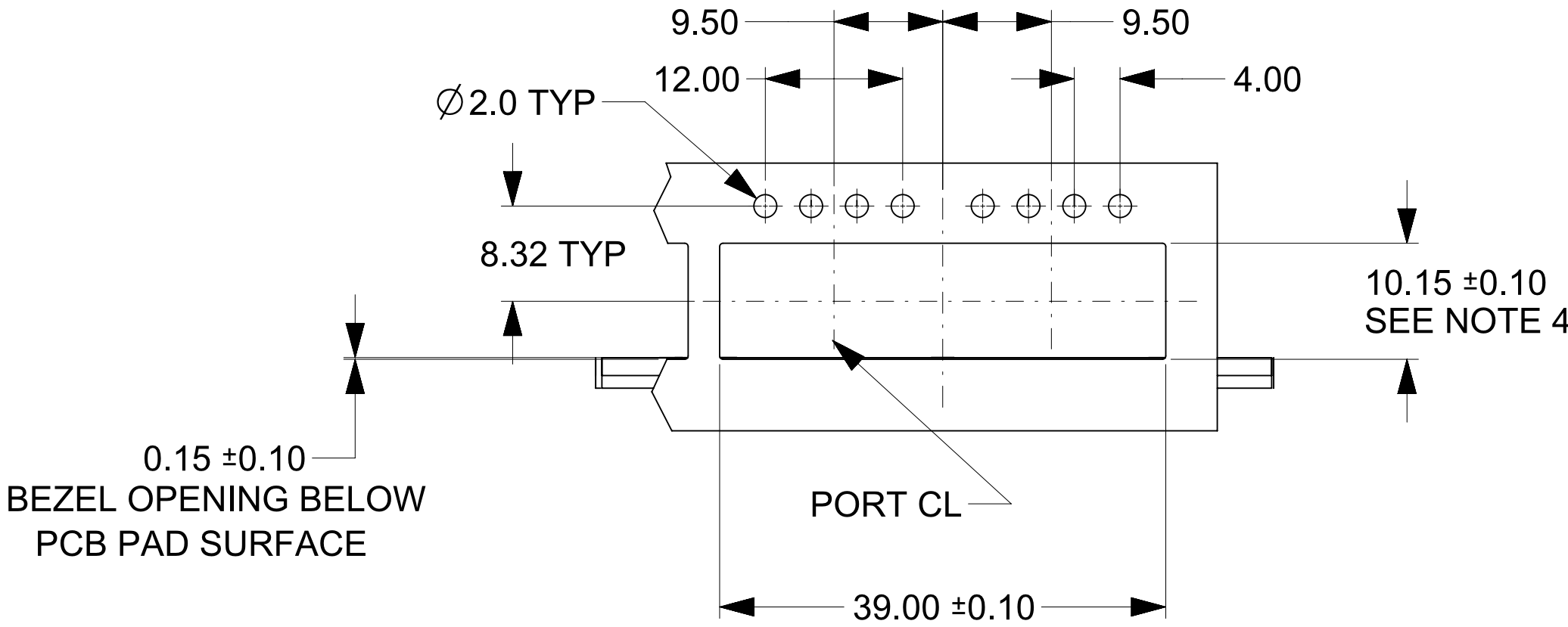
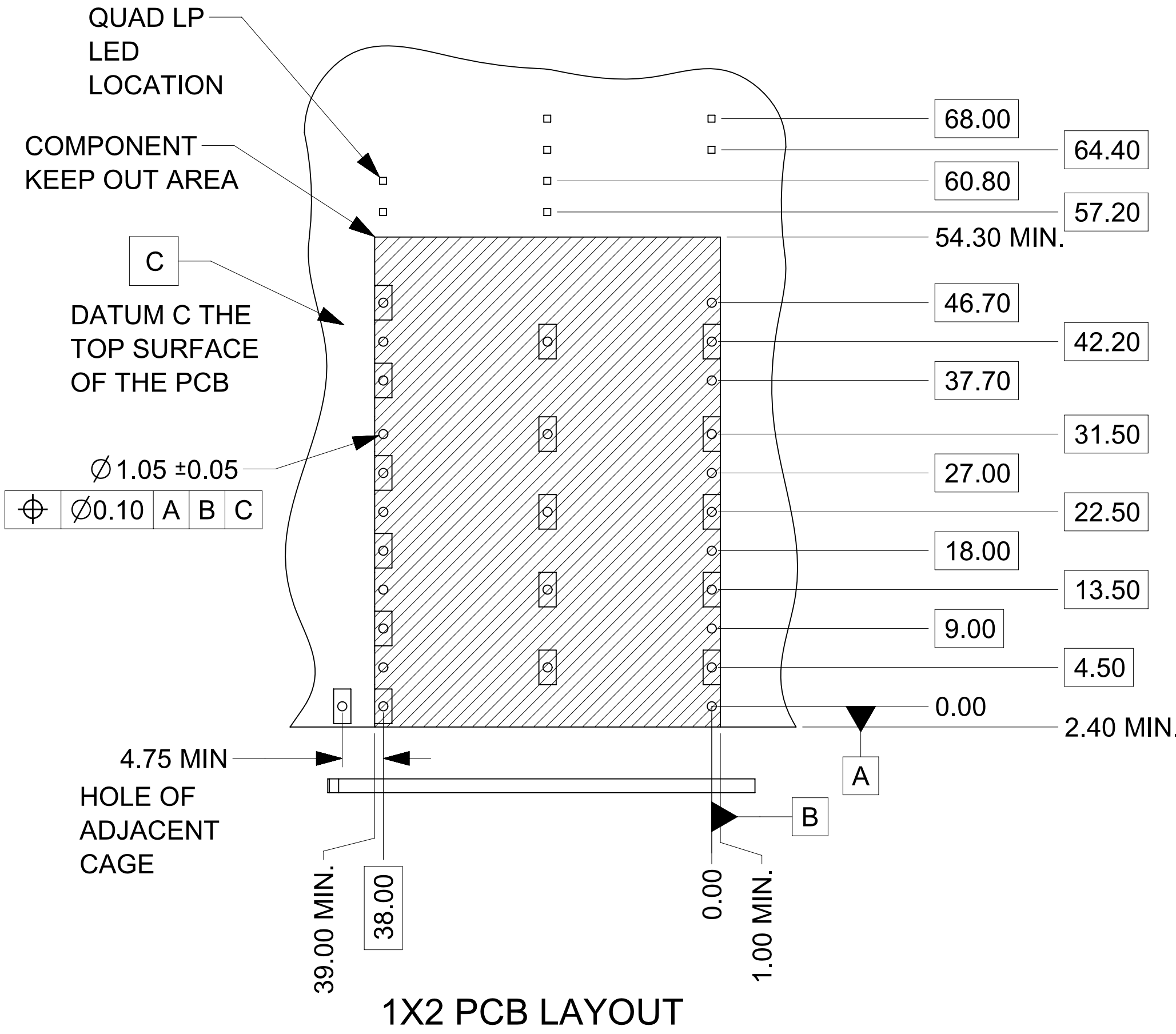
- NOTES:
- PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM X 4.0MM SQUARE)
 - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
 - HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
 - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.

FUNCTIONAL SYMBOLS $\frac{F}{A} = 0$ $\frac{F}{C} = 0$ $\frac{F}{P} = 0$ DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																
	DIMENSION UNITS MM		SCALE 2:1		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]				molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP								
	GENERAL TOLERANCES (UNLESS SPECIFIED)																
	ANGULAR TOL $\pm 0.5^\circ$																
4 PLACES $\pm$				STATUS: Production DRWN: Levy Li CHK'D: Roy (Yu Da) Liu APPR: Bill (Lie) Chen				2023-11-14 2024-03-04 2024-03-04				DOCUMENT NUMBER 1111310799 DOC TYPE PSD DOC PART 000 REVISION J1					
3 PLACES $\pm$																	
2 PLACES $\pm$																	
1 PLACE $\pm$																	
0 PLACES $\pm$																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION 		DRAWING D-SIZE		SERIES 111131		MATERIAL NUMBER GENERAL MARKET				CUSTOMER GENERAL MARKET		SHEET NUMBER 12 OF 17	

PCB LAYOUT FOR BELLY TO BELLY MOUNTING

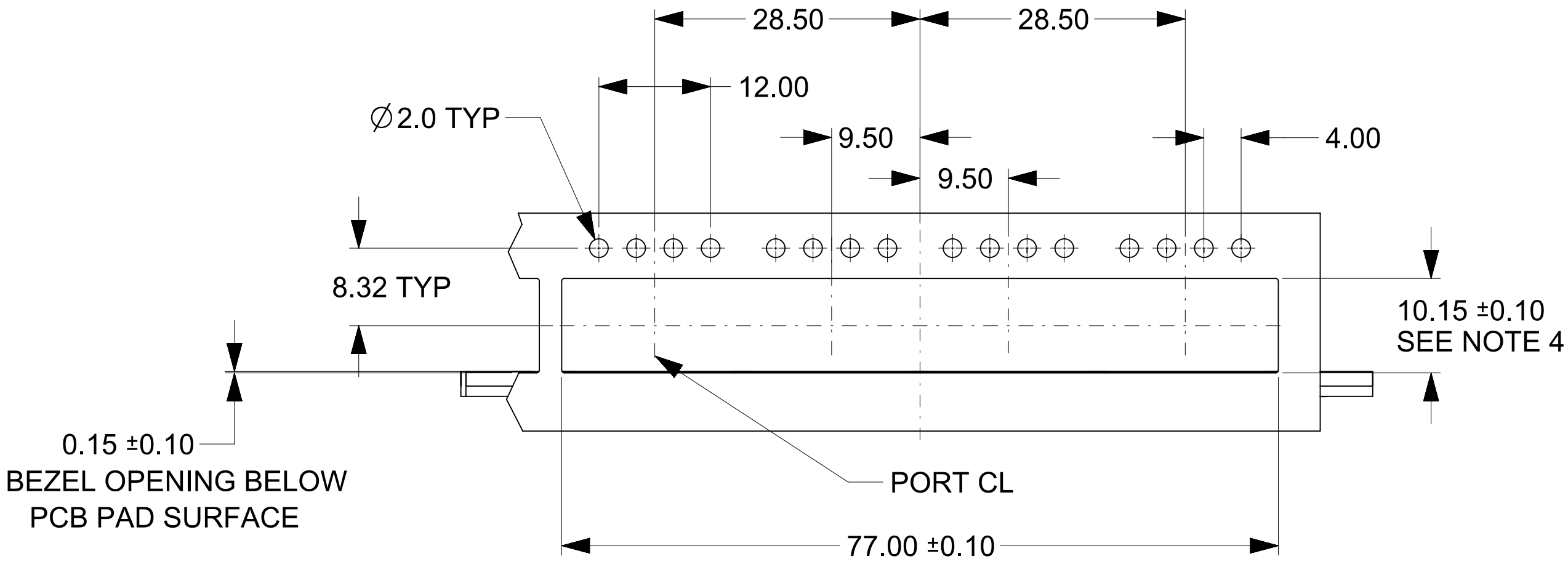
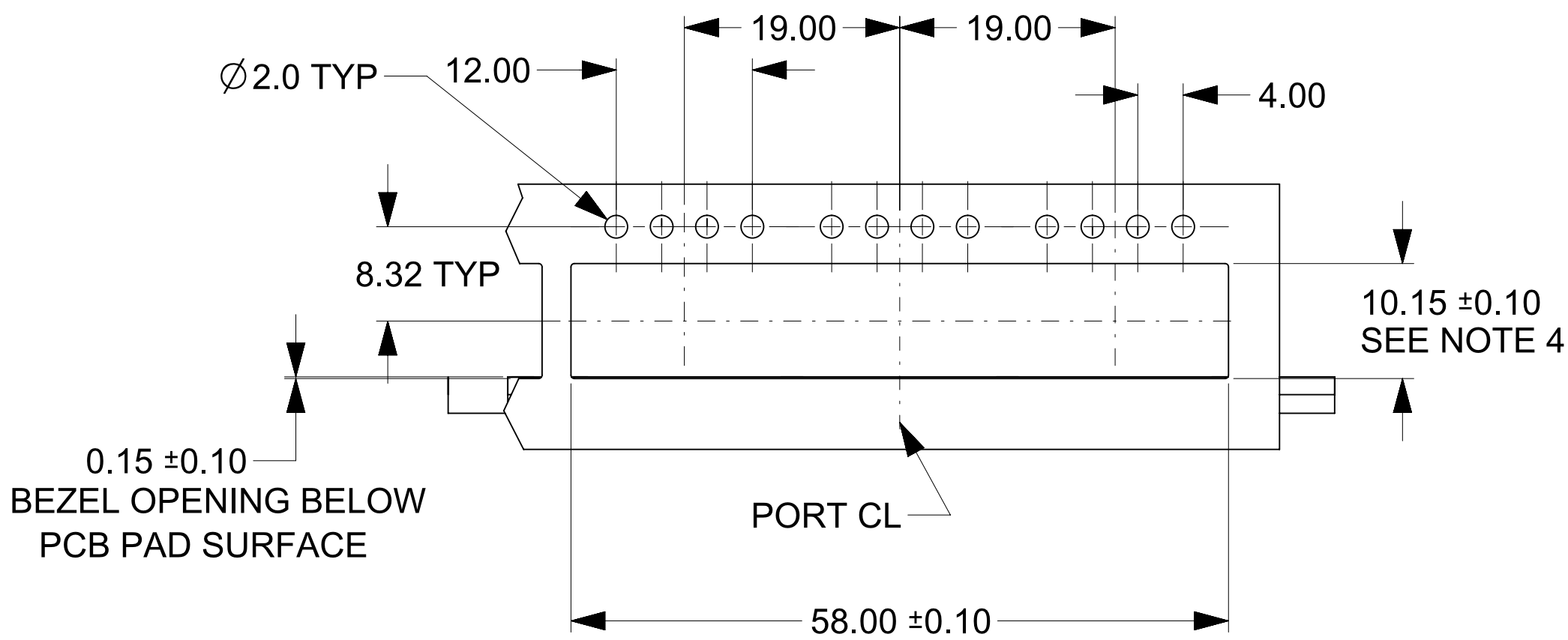
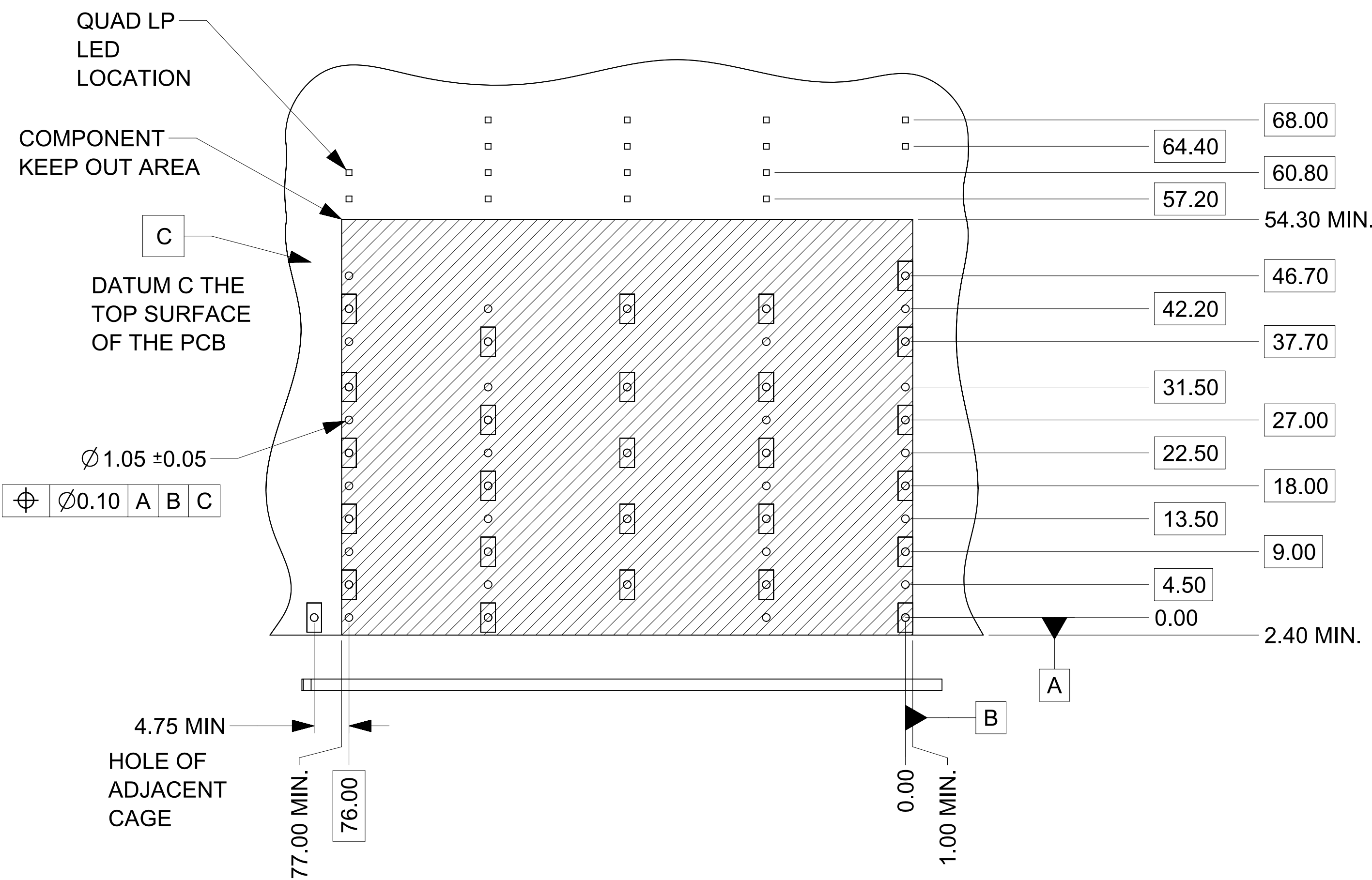
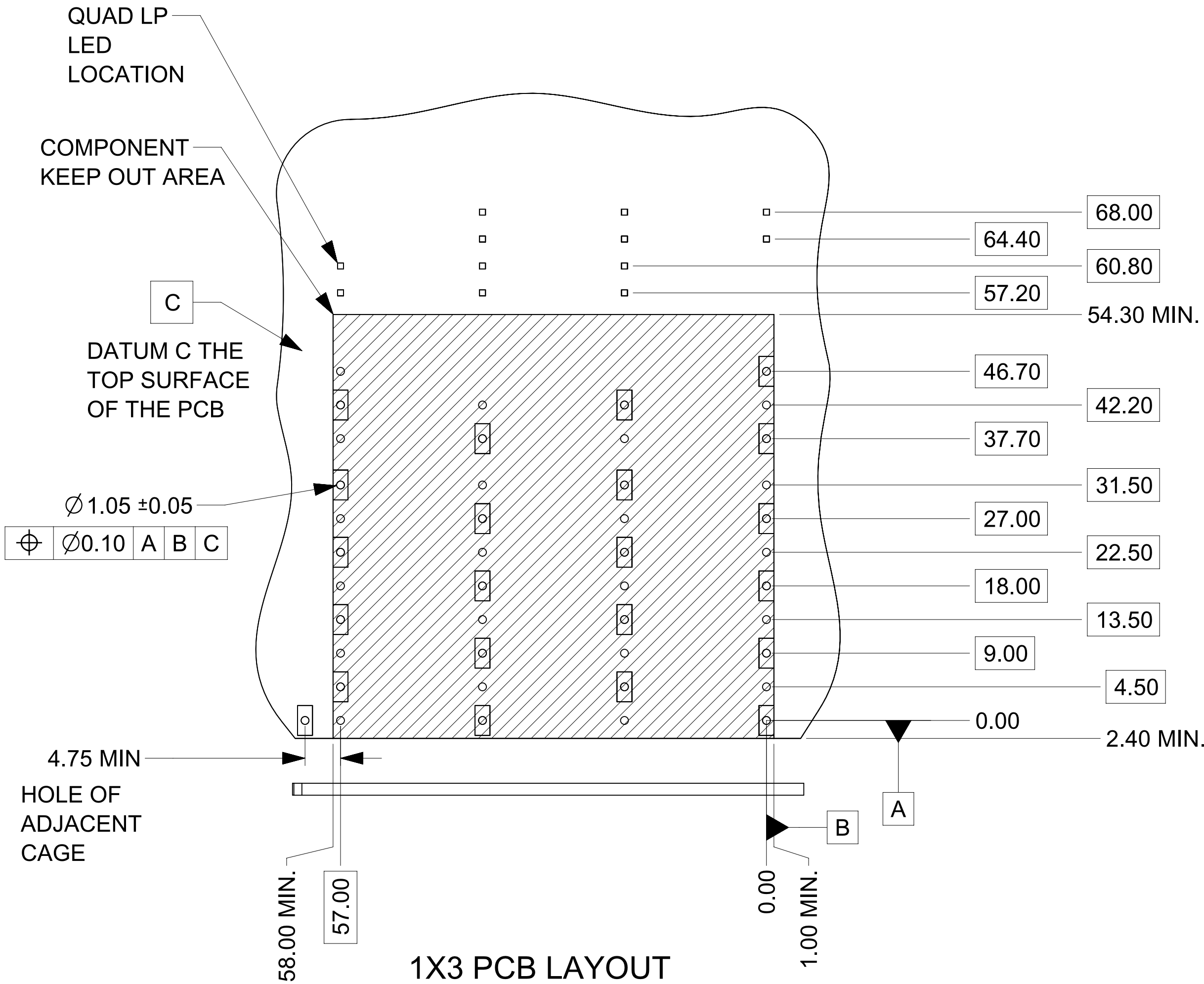


- NOTES:
- PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM X 4.0MM SQUARE)
 - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
 - HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
 - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.



THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
FUNCTIONAL SYMBOLS FA = 0 FC = 0 FP = 0 DIVISIONAL SYMBOLS		DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP PRODUCT SALES DRAWING				
		MM		2:1									
		GENERAL TOLERANCES (UNLESS SPECIFIED)											
		ANGULAR TOL ± 0.5°											
		4 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04			DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
		3 PLACES		±					1111310799		PSD	000	J1
		2 PLACES		±									
		1 PLACE		±									
		0 PLACES		±									
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER
				D-SIZE	111131			GENERAL MARKET		13 OF 17			

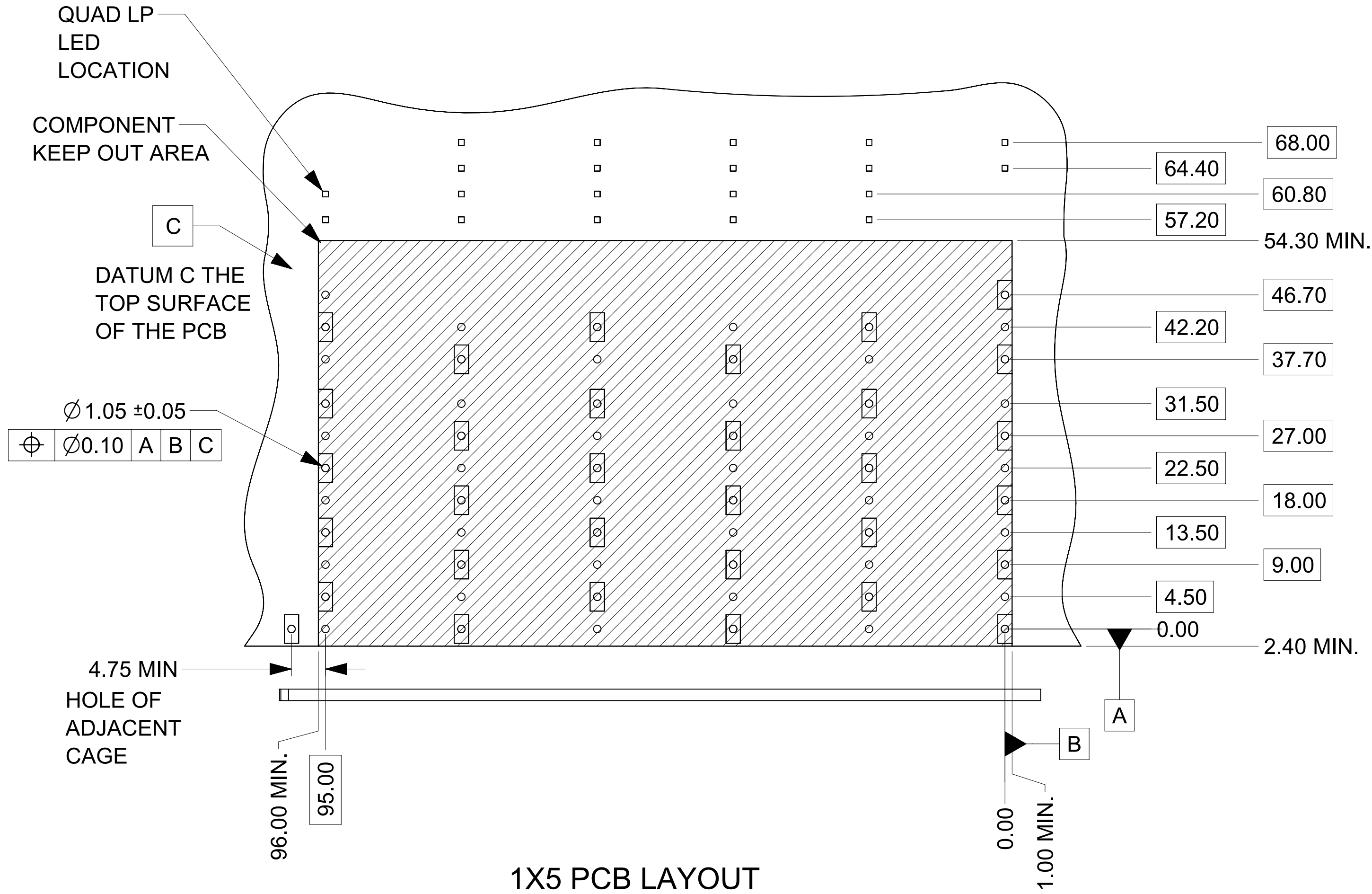
PCB LAYOUT FOR BELLY TO BELLY MOUNTING



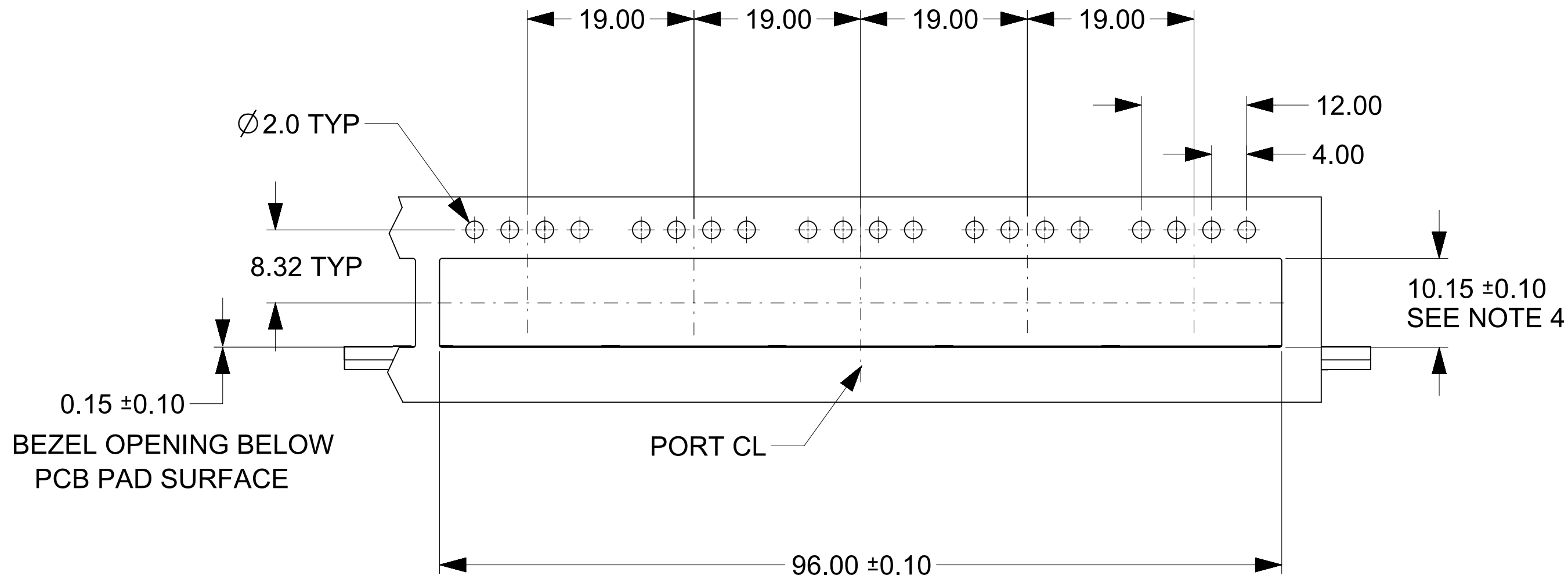
- NOTES:
- PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM - 4.0MM SQUARE)
 - RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
 - HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
 - PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.

FUNCTIONAL SYMBOLS F A = 0 F C = 0 F P = 0 DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION														
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]										
	MM		2:1												
	GENERAL TOLERANCES (UNLESS SPECIFIED)														
	ANGULAR TOL ± 0.5°				molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP PRODUCT SALES DRAWING DOCUMENT NUMBER 1111310799 DOC TYPE PSD DOC PART 000 REVISION J1										
	4 PLACES		±												
	3 PLACES		±												
	2 PLACES		±												
	1 PLACE		±												
	0 PLACES		±		STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04										
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						D-SIZE		111131				GENERAL MARKET		14 OF 17	

PCB LAYOUT FOR BELLY TO BELLY MOUNTING

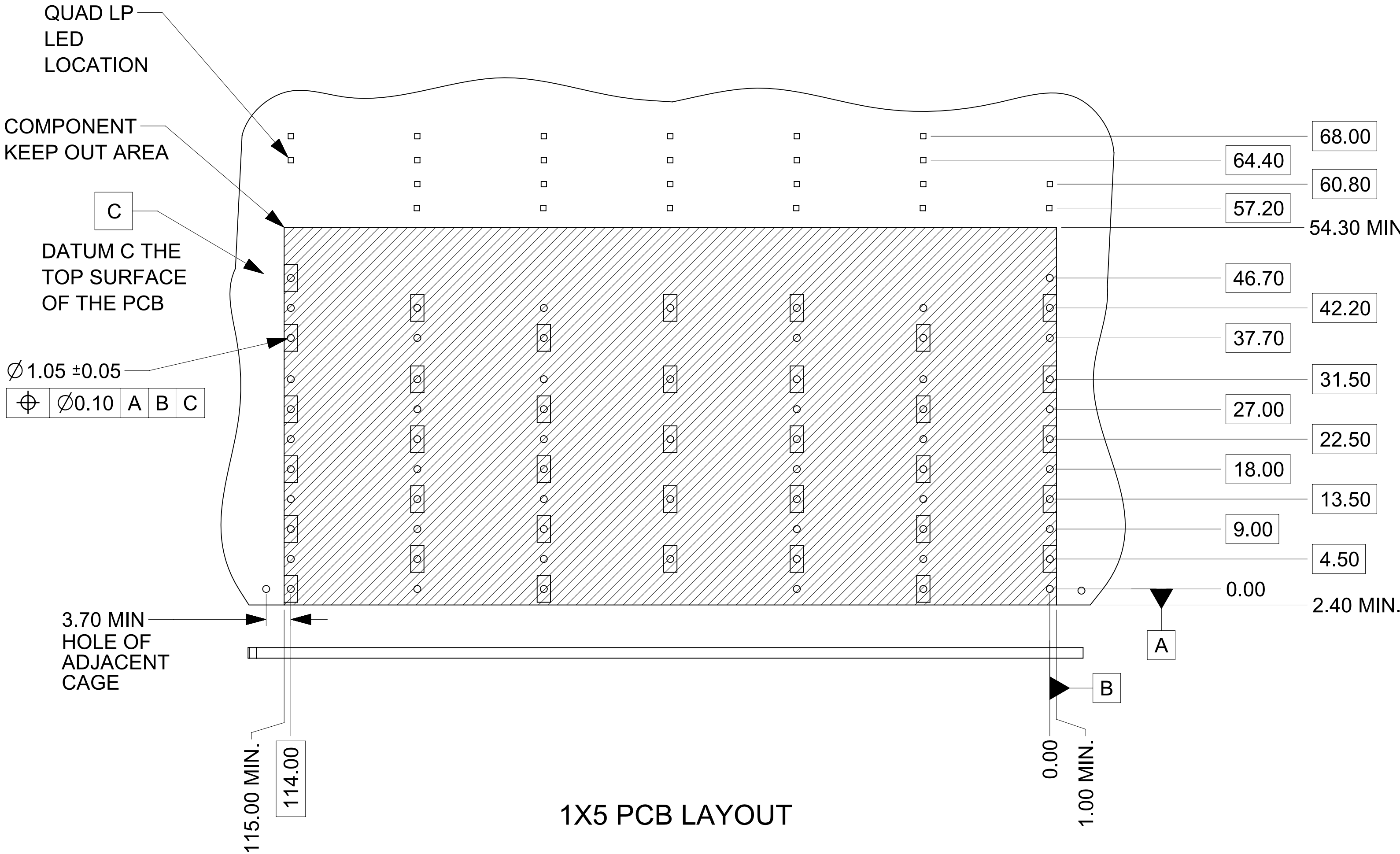


1X5 PCB LAYOUT

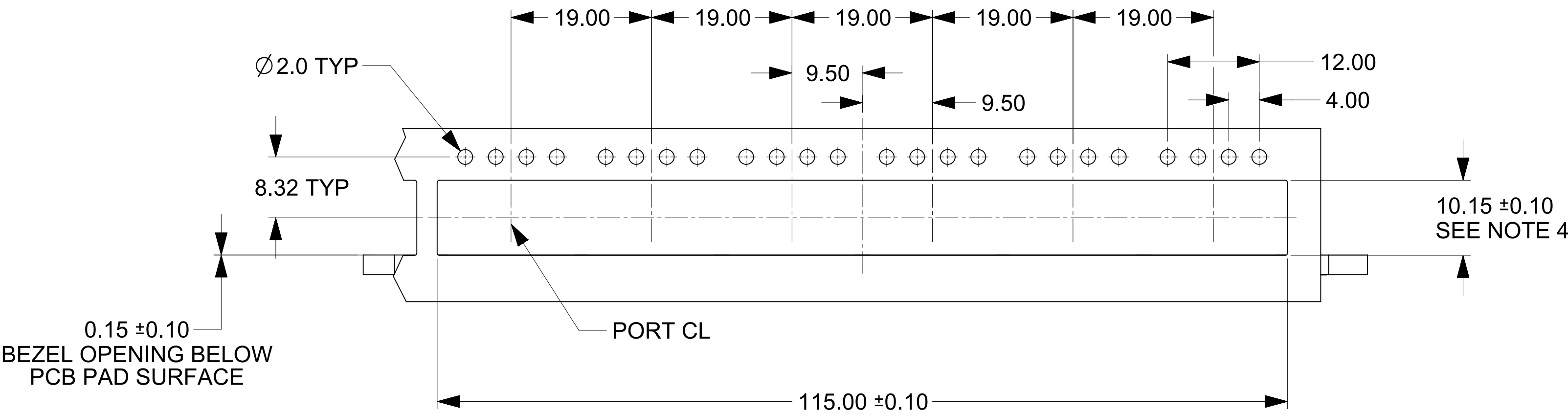


NOTES:

1. PADS AND VIAS GO TO CHASSIS GROUND. (RECOMMENDED PADS TO BE 2.0MM - 4.0mm SQUARE)
2. RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION Au, Ag OR Sn.
3. HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 19.00MM.
4. PCB THICKNESS VARIATION MUST BE CONSIDERED WHEN DETERMINING BEZEL OPENING, SIZE AND LOCATION.



1X5 PCB LAYOUT



FUNCTIONAL SYMBOLS F = 0 F = 0 F = 0 DIVISIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION														
	DIMENSION UNITS		SCALE		CURRENT REV DESC: 1. OBSOLETE F/G PN FOR NEARSTACK GEN 1.0 2 MODIFICATION NOTE 6 TO DELETE PN FOR GEN 1.0 [SHEET 1]			molex ENHANCED ZQSFP+ NEARSTACK TO PICO CLASP							
	MM		1:1												
	GENERAL TOLERANCES (UNLESS SPECIFIED)														
	ANGULAR TOL ± 0.5°														
	4 PLACES		±					STATUS: Production DRWN: Levy Li 2023-11-14 CHK'D: Roy (Yu Da) Liu 2024-03-04 APPR: Bill (Lie) Chen 2024-03-04			PRODUCT SALES DRAWING DOCUMENT NUMBER 1111310799 DOC TYPE PSD DOC PART 000 REVISION J1				
	3 PLACES		±												
	2 PLACES		±												
	1 PLACE		±												
	0 PLACES		±												
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						D-SIZE		111131				GENERAL MARKET		15 OF 17	

